Technical Description

The brief circuit description is listed as below:

1) **U1 acts as a WI-FI Module (WNZ7915).**
2) **U2/U3 acts as a Bluetooth Module (CC2541/CC2590).**
3) **U4/U6 acts as a LDO Regulator (RT9058/RT9193).**
4) **U5 acts as a step-down DC-DC Converter (RT8059).**
5) **U8 acts as a Camera DSP (SPCA6350M).**
6) **U13 acts as a MCU (ST864).**
7) **Y1/Y2 act as a Crystal for U8.**
8) **Y3/Y4 act as a Crystal for U2/U3.**
9) **Y5 acts as a Crystal for U1.**

WiFi Module
Antenna Type: Internal, Integral
Antenna Gain: 1.0dBi

Operating mode	Nominal Conducted Power	Production Tolerance
802.11b	14.5 dBm	+/- 3dB
802.11g	22.1 dBm	+/- 3dB
802.11n (HT20)	22.8 dBm	+/- 3dB

Bluetooth Module
Antenna Type: Internal, Integral
Antenna Gain: 2.555dBi

Operating mode	Nominal Radiated Power	Production Tolerance
Bluetooth 4.0 BLE	105.9 dBμV/m at 3m	+/- 3dB

2.4-GHz RF Front End, 14-dBm output power

FEATURES

- Seamless Interface to 2.4-GHz Low Power RF Devices from Texas Instruments
- Up to +14-dBm (25mW) Output Power
- 6-dB Typical Improved Sensitivity on CC24xx and CC2500, CC2510, and CC2511
- Few External Components
  - Integrated Switches
  - Integrated Matching Network
  - Integrated Balun
  - Integrated Inductors
  - Integrated PA
  - Integrated LNA
- Digital Control of LNA Gain by HGM Pin
- 100-nA in Power Down (EN = PAEN = 0)
- Low Transmit Current Consumption
  - 22-mA at 3-V for +12-dBm, PAE = 23%
- Low Receive Current Consumption
  - 3.4-mA for High Gain Mode
  - 1.8-mA for Low Gain Mode
- 4.6-dB LNA Noise Figure, including T/R Switch and external antenna match
- RoHS Compliant 4×4-mm QFN-16 Package
- 2.0-V to 3.6-V Operation

APPLICATIONS

- All 2.4-GHz ISM Band Systems
- Wireless Sensor Networks
- Wireless Industrial Systems
- IEEE 802.15.4 and ZigBee Systems
- Wireless Consumer Systems
- Wireless Audio Systems

DESCRIPTION

CC2590 is a cost-effective and high performance RF Front End for low-power and low-voltage 2.4-GHz wireless applications.

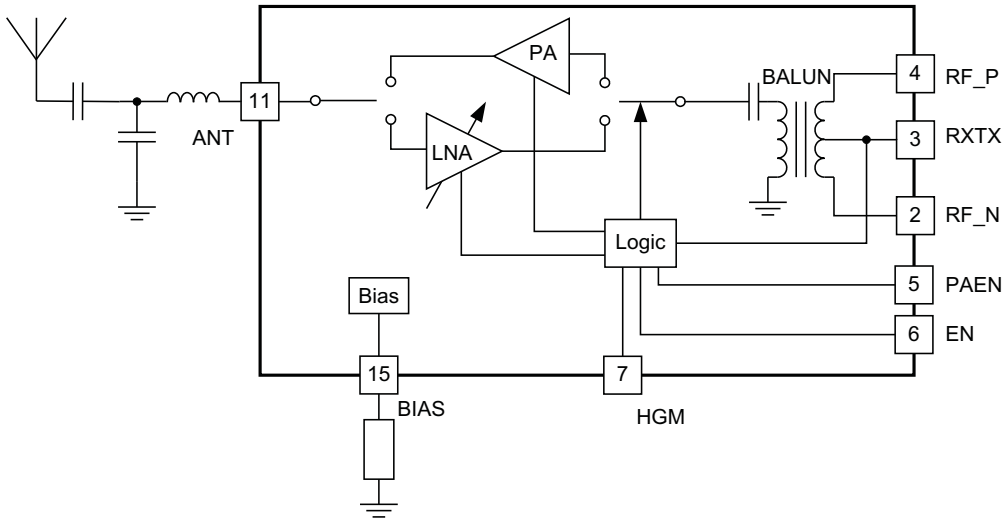
CC2590 is a range extender for all existing and future 2.4-GHz low-power RF transceivers, transmitters and System-on-Chip products from Texas Instruments.

CC2590 increases the link budget by providing a power amplifier for increased output power, and an LNA with low noise figure for improved receiver sensitivity.

CC2590 provides a small size, high output power RF design with its 4x4-mm QFN-16 package.

CC2590 contains PA, LNA, switches, RF-matching, and balun for simple design of high performance wireless applications.

CC2590 BLOCK DIAGRAM



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS

Under no circumstances must the absolute maximum ratings be violated. Stress exceeding one or more of the limiting values may cause permanent damage to the device.

PARAMETER		VALUE	UNIT
Supply voltage	All supply pins must have the same voltage	–0.3 to 3.6	V
Voltage on any digital pin		–0.3 to V_{DD} + 0.3, max 3.6	V
Input RF level		+10	dBm
Storage temperature range		–50 to 150	°C
Reflow soldering temperature	According to IPC/JEDEC J-STD-020	260	°C
ESD	Human Body Model, all pins except pin 10	2000	V
	Human Body Model, pin 10	1900	V
	Charged Device Model	1000	V

RECOMMENDED OPERATING CONDITIONS

The operating conditions for CC2590 are listed below.

PARAMETER		MIN	MAX	UNIT
Ambient temperature range		–40	85	°C
Operating supply voltage		2.0	3.6	V
Operating frequency range		2400	2483.5	MHz

ELECTRICAL CHARACTERISTICS

T_C = 25°C, V_{DD} = 3.0V , f_{RF}= 2440MHz (unless otherwise noted). Measured on CC2590EM reference design including external matching components.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Receive current, High Gain Mode	HGM = 1		3.4	4.0	mA
Receive current, Low Gain Mode	HGM = 0		1.8	2.0	mA
Transmit current	P_{IN} = 0.5 dBm, P_{OUT} = 12.2 dBm		22.1		mA
	P_{IN} = –3.5 dBm, P_{OUT} = 10.0 dBm		16.8		mA
Transmit current	No input signal		8.0	10.0	mA
Power down current	EN = PAEN = 0		0.1	0.3	µA
High input level (control pins)	EN, PAEN, HGM, RXTX	1.3		V_{DD}	V
Low input level (control pins)	EN, PAEN, HGM, RXTX			0.3	V
Power down - Receive mode switching time			1.4		µs
Power down - Transmit mode switching time			0.8		µs
RF Receive					
Gain, High Gain Mode	HGM = 1		11.4		dB
Gain, Low Gain Mode	HGM = 0		0		dB
Gain variation, 2400 – 2483.5 MHz, High Gain Mode	HGM = 1		1.2		dB
Gain variation, 2.0V – 3.6V, High Gain Mode	HGM = 1		1.7		dB
Noise figure, High Gain Mode	HGM = 1, including internal T/R switch and external antenna match		4.6		dB
Input 1 dB compression, High Gain Mode	HGM = 1		–21		dBm

ELECTRICAL CHARACTERISTICS (continued)

T_C = 25°C, V_{DD} = 3.0V , f_{RF}= 2440MHz (unless otherwise noted). Measured on CC2590EM reference design including external matching components.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Input IP3, High Gain Mode	HGM = 1		–9		dBm
Input reflection coefficient, S11	HGM = 1, measured at antenna port		–19		dB
RF Transmit					
Gain			14.1		dB
Output power, P_{OUT}	P_{IN} = 4.5 dBm		13.8		dBm
	P_{IN} = 0.5 dBm		12.2		dBm
	P_{IN} = -3.5 dBm		10.0		dBm
Power Added Efficiency, PAE	P_{IN} = 0.5 dBm		23.5		%
Output 1 dB compression			10.4		dBm
Output IP3			23		dBm
Output power variation over frequency	2400 – 2483.5 MHz, P_{IN} = 0.5 dBm		0.3		dB
Output power variation over power supply	2.0V – 3.6V , P_{IN} = 0.5 dBm		3.2		dB
Output power variation over temperature	-40°C – 85°C, P_{IN} = 0.5 dBm		1.1		dB
2nd harmonic power	The 2nd harmonic can be reduced to below regulatory limits by using an external LC filter and antenna. See application note AN032 for regulatory requirements.		–14		dBm
3rd harmonic power	The 3rd harmonic can be reduced to below regulatory limits by using an external LC filter and antenna. See application note AN032 for regulatory requirements.		–28		dBm

DEVICE INFORMATION

The CC2590 pinout and description are shown in Figure 1 and Table 1, respectively.

PIN AND I/O CONFIGURATION
(TOP VIEW)

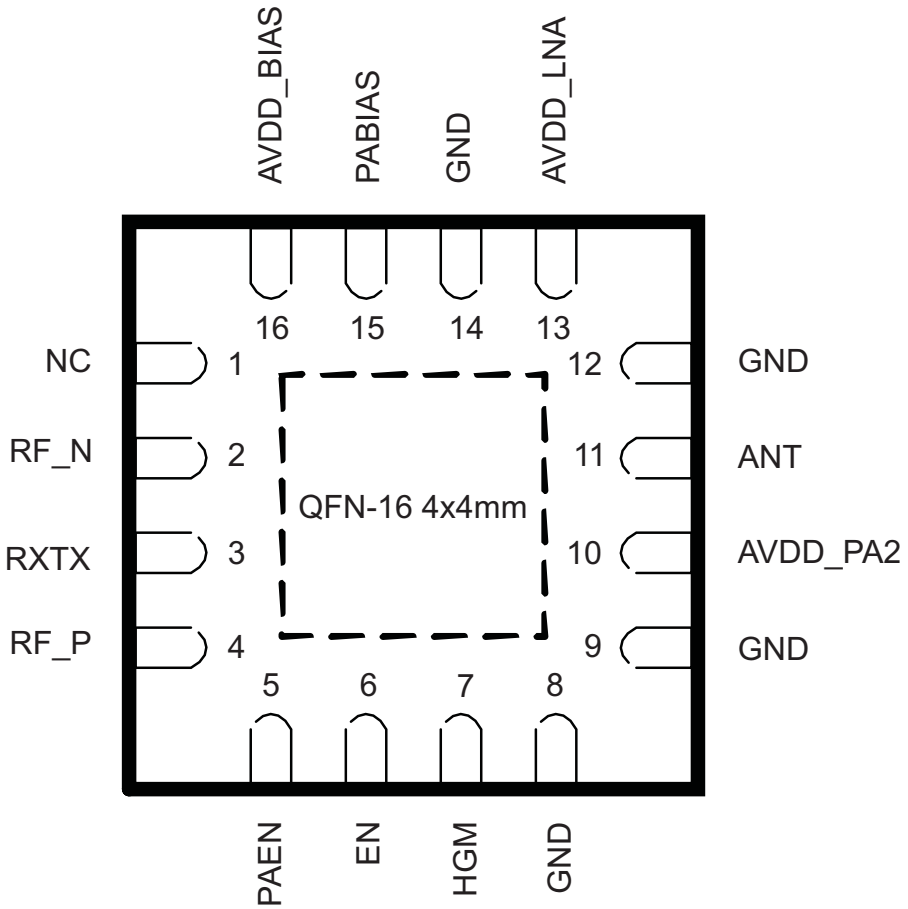


Figure 1.

NOTE:

The exposed die attach pad **must** be connected to a solid ground plane as this is the primary ground connection for the chip. Inductance in vias to the pad should be minimized. It is highly recommended to follow the reference layout. Changes will alter the performance. Also see the PCB landpattern information in this data sheet.

For best performance, minimize the length of the ground vias, by using a 4-layer PCB with ground plane as layer 2 when CC2590 is mounted onto layer 1.

Table 1. PIN FUNCTIONS

PIN		TYPE	DESCRIPTION
NO.	NAME		
—	GND	Ground	The exposed die attach pad must be connected to a solid ground plane. See CC2590EM reference design for recommended layout.
1	NC		Not Connected
2	RF_N	RF	RF interface towards CC24xx or CC25xx device.
3	RXTX	Analog/Control	RXTX switching voltage when connected to CC24xx devices. See Table 3, Table 4, and Table 5 for details.
4	RF_P	RF	RF interface towards CC24xx or CC25xx device
5	PAEN	Digital Input	Digital control pin. See Table 3, Table 4, and Table 5 for details.
6	EN	Digital Input	Digital control pin. See Table 3, Table 4, and Table 5 for details.
7	HGM	Digital Input	Digital control pin. HGM=1 → Device in High Gain Mode HGM=0 → Device in Low Gain Mode (RX only)
8, 9, 12, 14	GND	Ground	Secondary ground connections. Should be shorted to the die attach pad on the top PCB layer.
10	AVDD_PA2	Power	2.0-V – 3.6-V Power. PCB trace to this pin serves as inductive load to PA. See CC2590EM reference design for recommended layout.
11	ANT	RF	Antenna interface.
13	AVDD_LNA	Power	2.0-V – 3.6-V Power. PCB trace to this pin serves as inductive load to LNA. See CC2590EM reference design for recommended layout.
15	BIAS	Analog	Biasing input. Resistor between this node and ground sets bias current to PAs.
16	AVDD_BIAS	Power	2.0-V – 3.6-V Power.

CC2590EM Evaluation Module

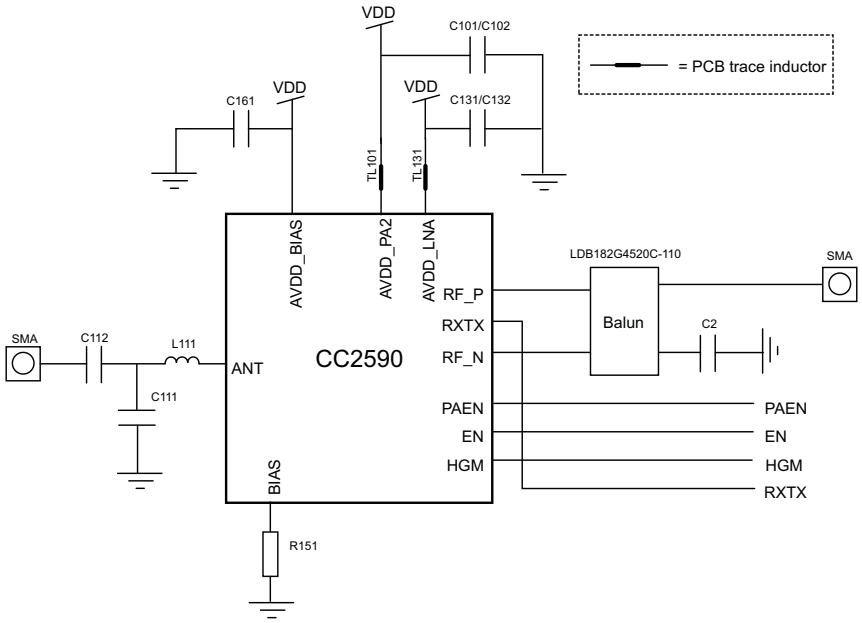


Figure 2. CC2590EM Evaluation Module

Table 2. List of Materials (See CC2590EM Reference Design)

DEVICE	FUNCTION	VALUE
L112	Part of antenna match.	1.5 nH: LQW15AN1N5B00 from Murata
C111	Part of antenna match.	0.5 pF, GRM1555C1HR50BZ01 from Murata
C112	DC block.	47 pF, GRM1555C1H470JZ01 from Murata
C161	Decoupling capacitor.	1 nF: GRM1555C1H102JA01 from Murata
C101/C102	Decoupling. Will affect PA resonance. See CC2590EM reference design for placement.	27 pF || 1 nF. The smallest cap closest to CC2590. 27 pF: GRM1555C1H270JZ01 from Murata 1 nF: GRM1555C1H102JA01 from Murata
C131/C132	Decoupling. Will affect LNA resonance. See CC2590EM reference design for placement.	18 pF || 1 nF. The smallest cap closest to CC2590. 18 pF: GRM1555C1H180JZ01 from Murata 1 nF: GRM1555C1H102JA01 from Murata
C2	Decoupling of external balun	1 nF: LWQ15AN1N5B00 from Murata
TL101 (1)	Transmission line. Will affect PA resonance. (simulated inductance: 0.87nH)	See CC2590EM reference design. Transmission line: Length ≈ 40 mil, Width = 8 mil
TL131	Transmission line. Will affect LNA resonance. (simulated inductance: 1.64nH)	See CC2590EM reference design. Transmission line: Length ≈ 100 mil, Width = 8 mil
R151	Bias resistor	4.3 kΩ: RK73H1ETTP4301F from Koa

(1) Transmission lines are measured from edge of pad of the CC2590 footprint to edge of pad of DC coupling capacitor. The length of the transmission lines depend on the distance to the ground plane. If another PCB stack up is chosen the length of the transmission lines needs to be adjusted.

PCB description: 4 layer PCB 1.6mm

Copper 1: 35 µm
Dielectric 1-2: 0.35 mm (e.g. 2x Prepreg 7628 AT05 47% Resin)
Copper 2: 18 µm
Dielectric 2-3: 0.76 mm (4 x 7628M 43% Resin)
Copper 3: 18 µm
Dielectric 3-4: 0.35 mm (e.g. 2x Prepreg 7628 AT05 47% Resin)
Copper 4: 35 µm

DE104iML or equivalent substrate (Resin contents around 45%, which gives Er=4.42 at 2.4GHz, TanD=0.016)

TYPICAL CHARACTERISTICS

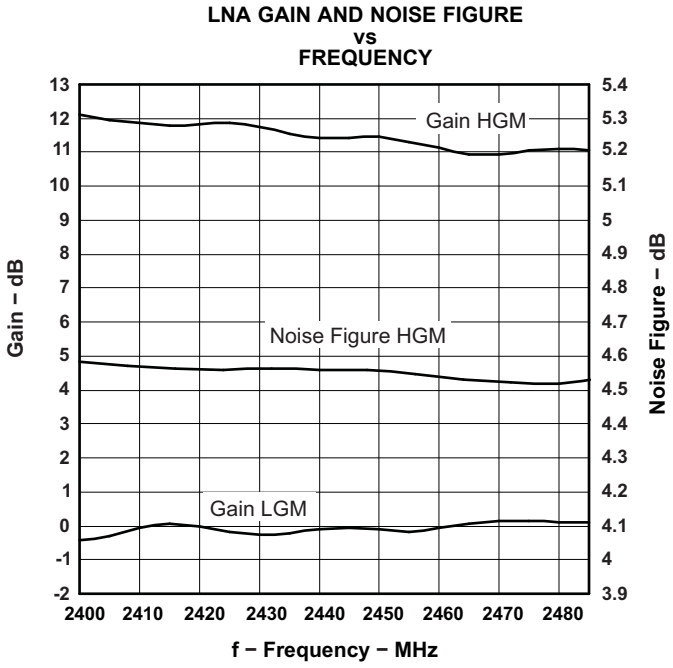


Figure 3.

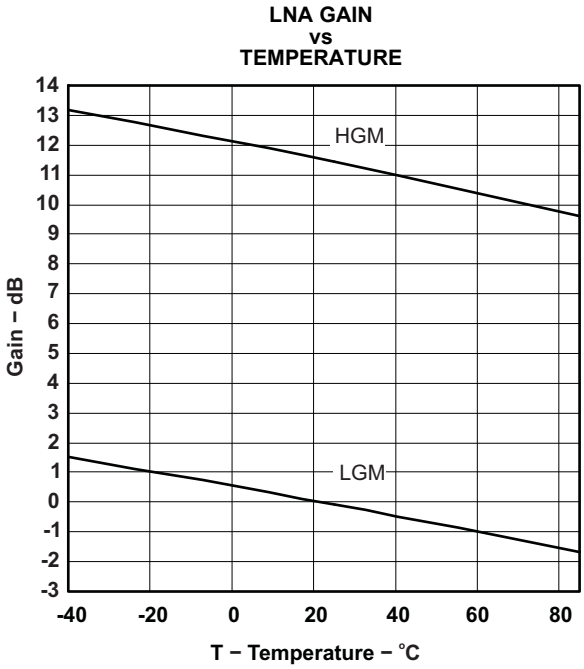


Figure 4.

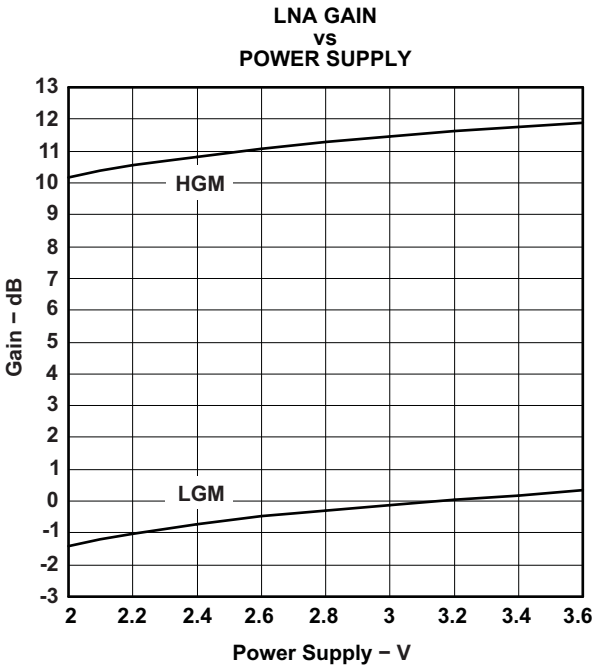


Figure 5.

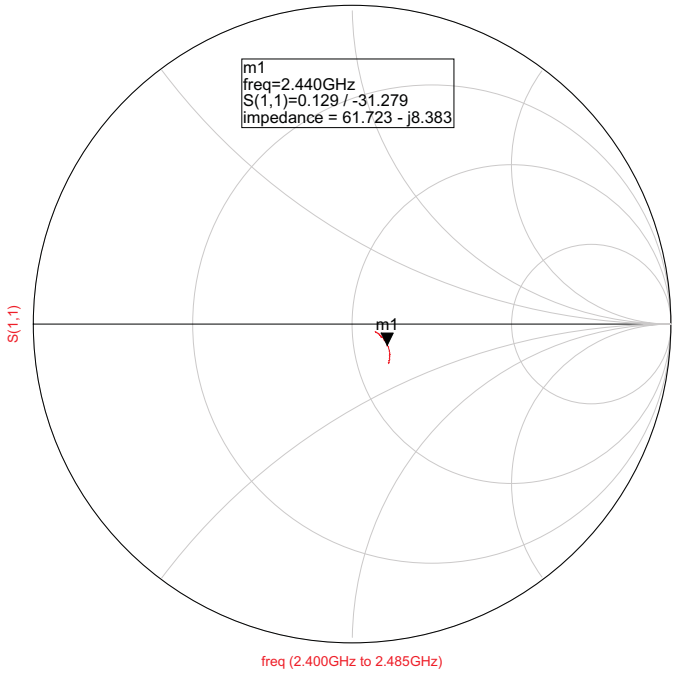


Figure 6. Input Impedance of LNA Measured from Antenna Port on CC2590EM

TYPICAL CHARACTERISTICS (continued)

OUTPUT POWER, PAE AND CURRENT CONSUMPTION vs INPUT POWER

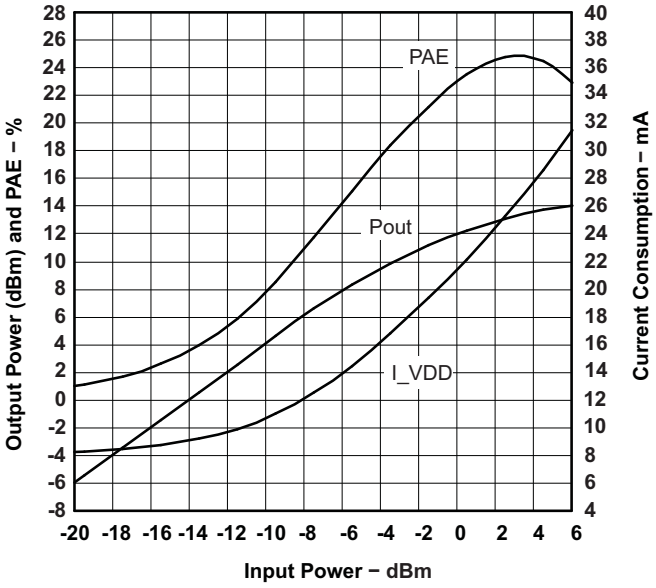


Figure 7.

OUTPUT POWER, PAE AND CURRENT CONSUMPTION vs FREQUENCY

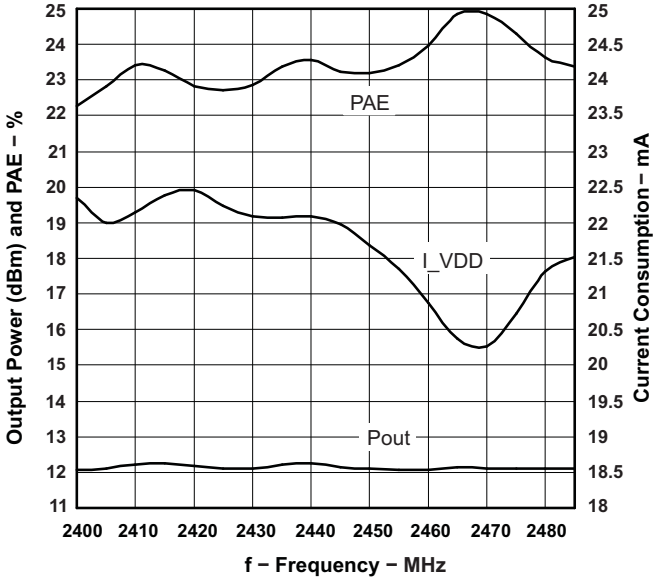


Figure 8.

OUTPUT POWER, PAE AND CURRENT CONSUMPTION vs TEMPERATURE

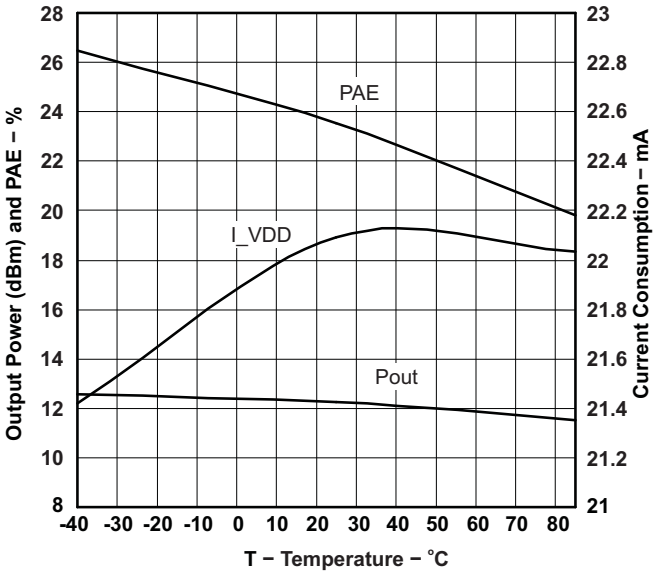


Figure 9.

OUTPUT POWER, PAE AND CURRENT CONSUMPTION vs POWER SUPPLY

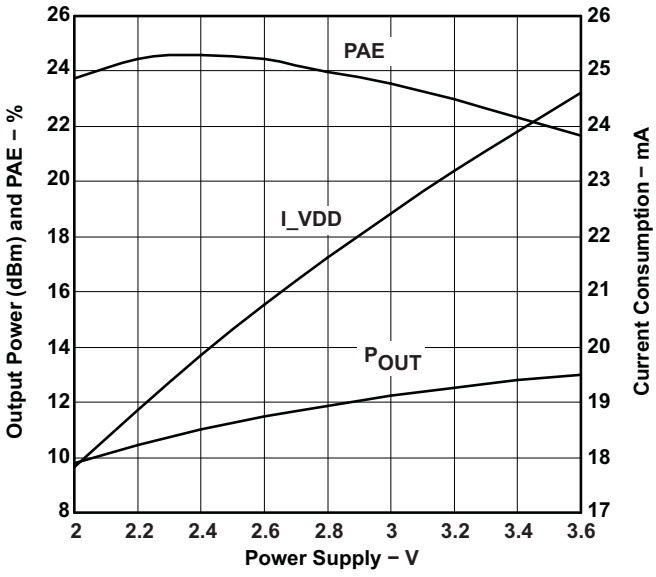


Figure 10.

Controlling the Output Power from CC2590

The output power of CC2590 is controlled by controlling the input power. The CC2590 PA is designed to work in compression (class AB), and the best efficiency is reached when a strong input signal is applied.

Input Levels on Control Pins

The four digital control pins (PAEN, EN, HGM, RXTX) have built-in level-shifting functionality, meaning that if the CC2590 is operating from a 3.6-V supply voltage, the control pins will still sense 1.6-V - 1.8-V signals as logical '1'.

An example of the above would be that RXTX is connected directly to the RXTX pin on CC24xx, but the global supply voltage is 3.6-V. The RXTX pin on CC24xx will switch between 0-V (RX) and 1.8-V(TX), which is still a high enough voltage to control the mode of CC2590.

The input voltages should however not have logical '1' level that is higher than the supply.

Connecting CC2590 to a CC24xx Device

Table 3. Control Logic for Connecting CC2590 to a CC24xx Device

PAEN = EN	RXTX	HGM	MODE OF OPERATION
0	X	X	Power Down
1	0	0	RX Low Gain Mode
1	0	1	RX High Gain Mode
1	1	X	TX

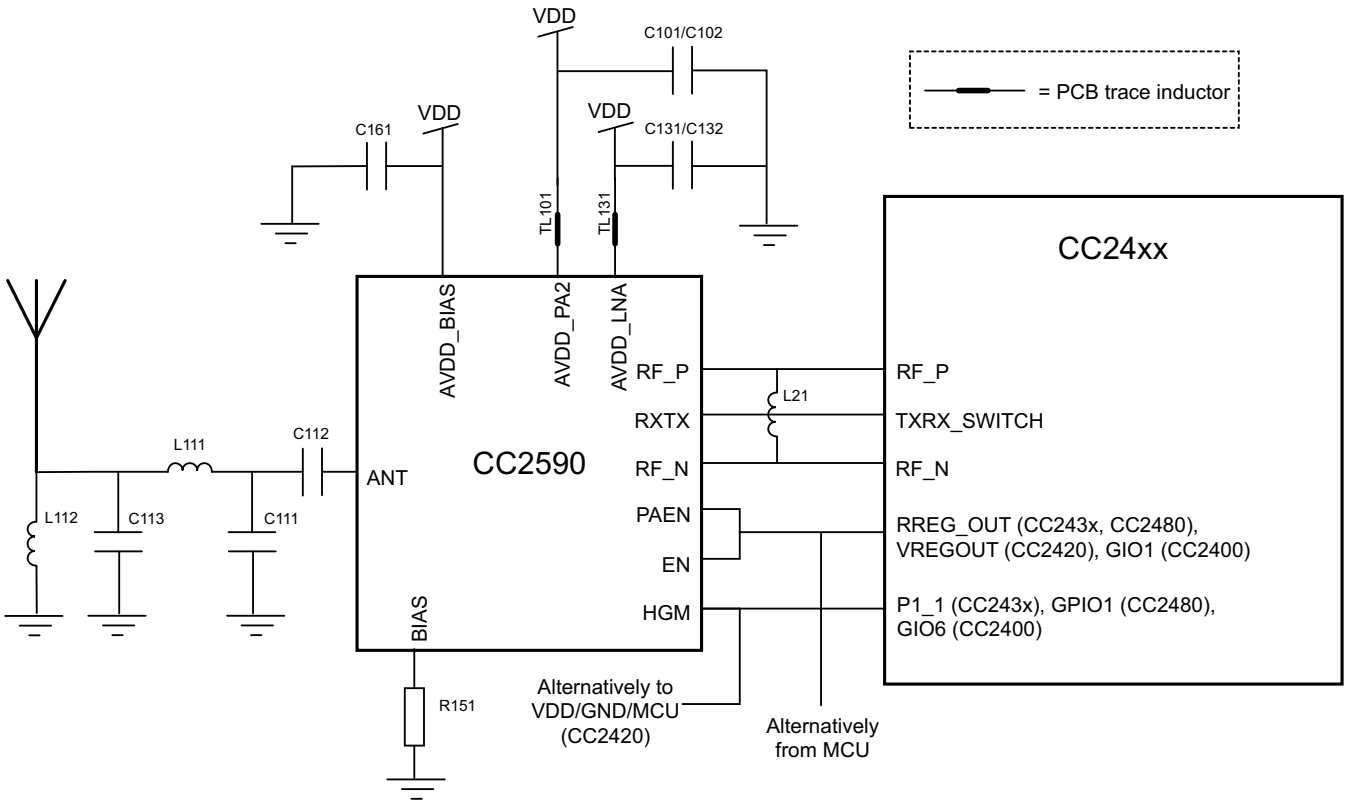


Figure 11. CC2590 + CC24xx Application Circuit

Connecting CC2590 to the CC2500, CC2510, or CC2511 Device

Table 4. Control Logic for Connecting CC2590 to a CC2500/10/11 Devices

PAEN	EN	RXTX	HGM	MODE OF OPERATION
0	0	NC	X	Power Down
0	1	NC	0	RX Low Gain Mode
0	1	NC	1	RX High Gain Mode
1	0	NC	X	TX
1	1	NC	X	Not allowed

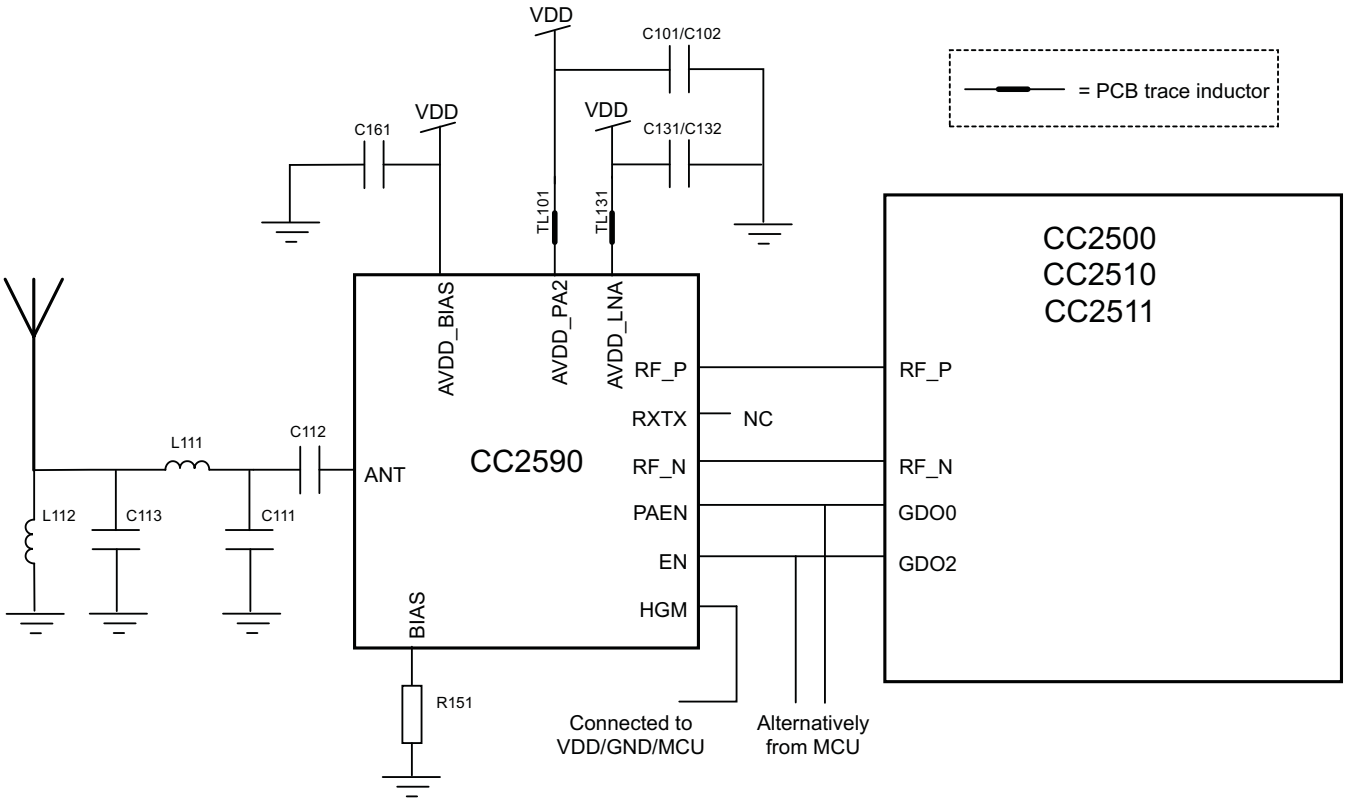


Figure 12. CC2590 + CC2500/10/11 Device Application Circuit

Connecting CC2590 to a CC2520 Device

Table 5. Control Logic for Connecting CC2590 to a CC2520 Device

PAEN	EN	RXTX	HGM	MODE OF OPERATION
0	0	NC	X	Power Down
0	1	NC	0	RX Low Gain Mode
0	1	NC	1	RX High Gain Mode
1	0	NC	X	TX
1	1	NC	X	Not allowed

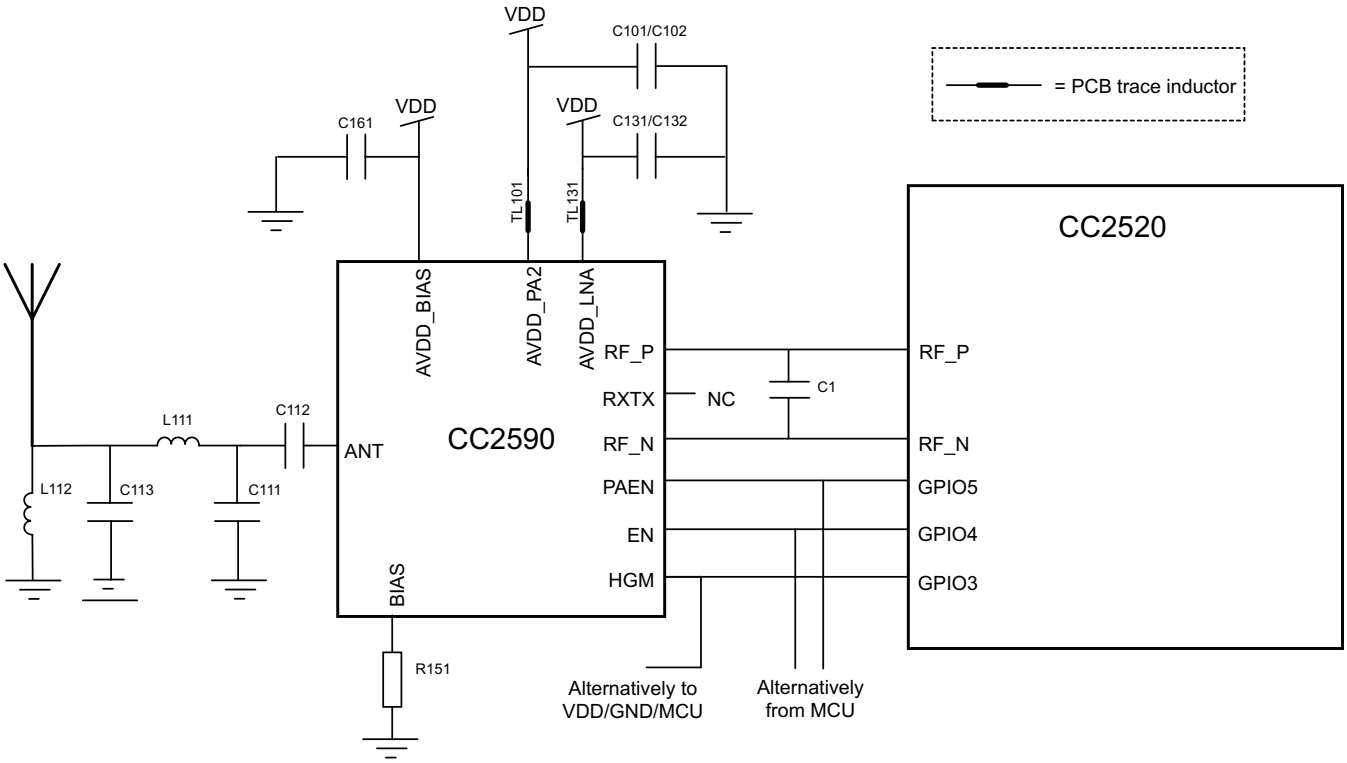


Figure 13. CC2590 + CC2520 Application Circuit

PCB Layout Guidelines

The exposed die attach pad must be connected to a solid ground plane as this is the primary ground connection for the chip. Inductance in vias to the pad should be minimized. It is highly recommended to follow the reference layout. Changes will alter the performance. Also see the PCB landpattern information in this data sheet. For best performance, minimize the length of the ground vias, by using a 4-layer PCB with ground plane as layer 2 when CC2590 is mounted onto layer 1.

PCB trace inductors are used to be able to optimize the inductance value, and they are too small to be replaced by discrete inductors. The placement of the power supply decoupling capacitors C101/C102 and C131/C132 are important to set the PCB trace inductance values accurately.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CC2590RGVR	ACTIVE	VQFN	RGV	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | Call TI	Level-2-260C-1 YEAR	-40 to 85	CC2590	Samples
CC2590RGVRG4	ACTIVE	VQFN	RGV	16	2500	Green (RoHS & no Sb/Br)	Call TI	Level-2-260C-1 YEAR	-40 to 85	CC2590	Samples
CC2590RGVT	ACTIVE	VQFN	RGV	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU | Call TI	Level-2-260C-1 YEAR	-40 to 85	CC2590	Samples
CC2590RGVTG4	ACTIVE	VQFN	RGV	16	250	Green (RoHS & no Sb/Br)	Call TI	Level-2-260C-1 YEAR	-40 to 85	CC2590	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

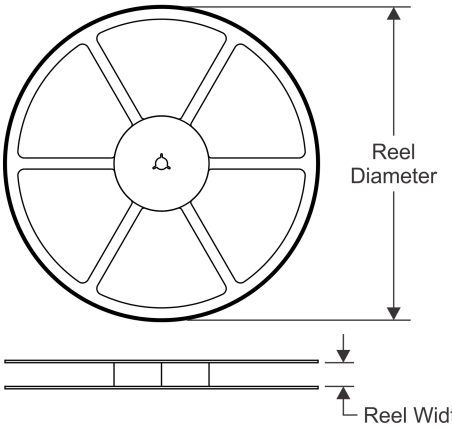
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

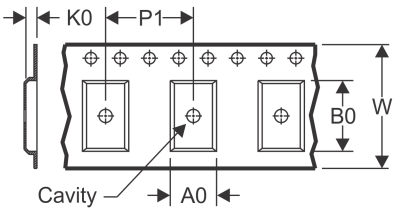
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

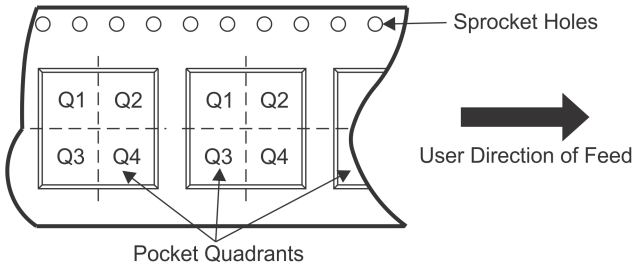


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

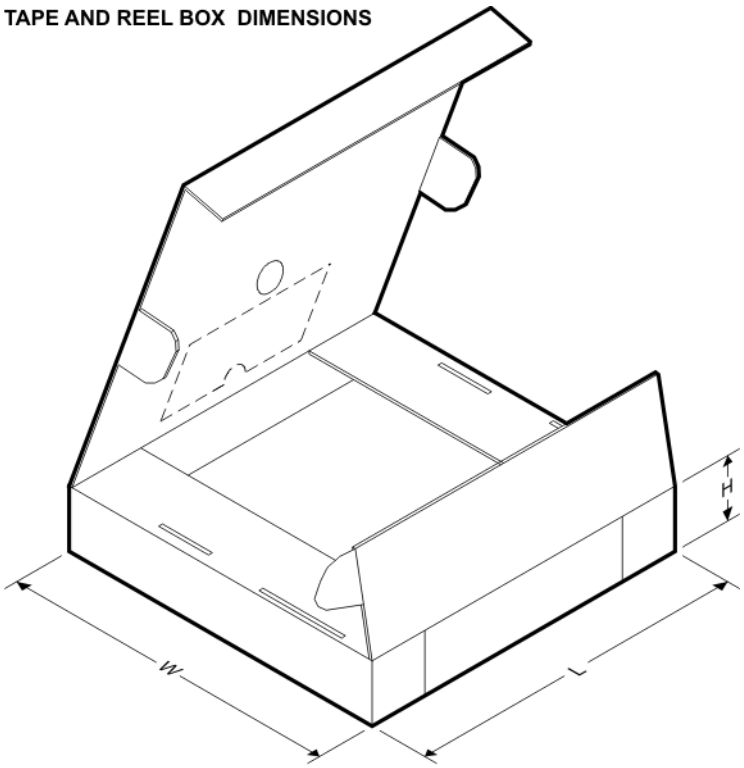
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CC2590RGVR	VQFN	RGV	16	2500	330.0	12.4	4.3	4.3	1.5	8.0	12.0	Q2
CC2590RGVT	VQFN	RGV	16	250	180.0	12.4	4.3	4.3	1.5	8.0	12.0	Q2

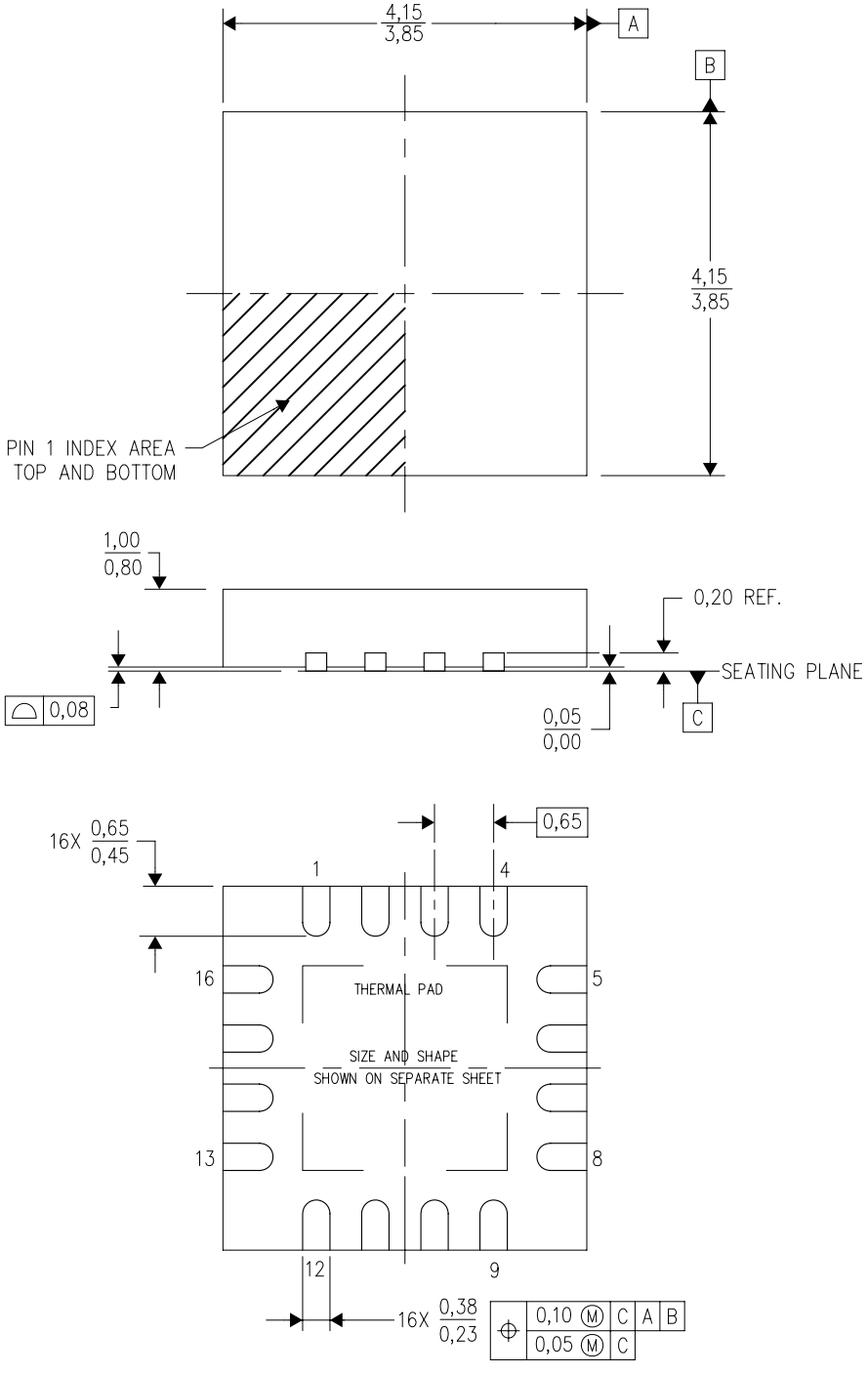
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CC2590RGVR	VQFN	RGV	16	2500	338.1	338.1	20.6
CC2590RGVT	VQFN	RGV	16	250	210.0	185.0	35.0

RGV (S–PVQFN–N16) PLASTIC QUAD FLATPACK NO–LEAD



NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Quad Flatpack, No–leads (QFN) package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
F. Falls within JEDEC MO–220.

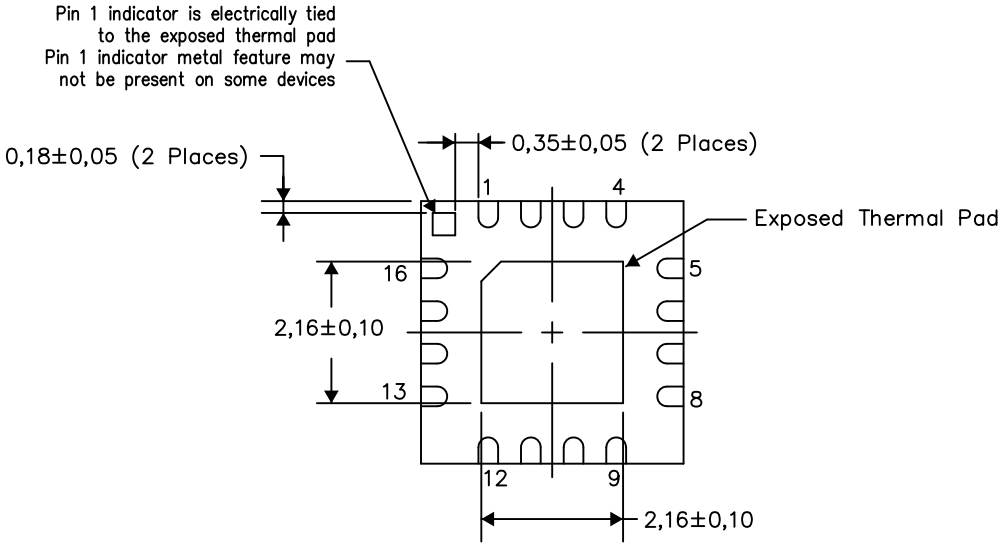
RGV (S–PVQFN–N16) PLASTIC QUAD FLATPACK NO–LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No–Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



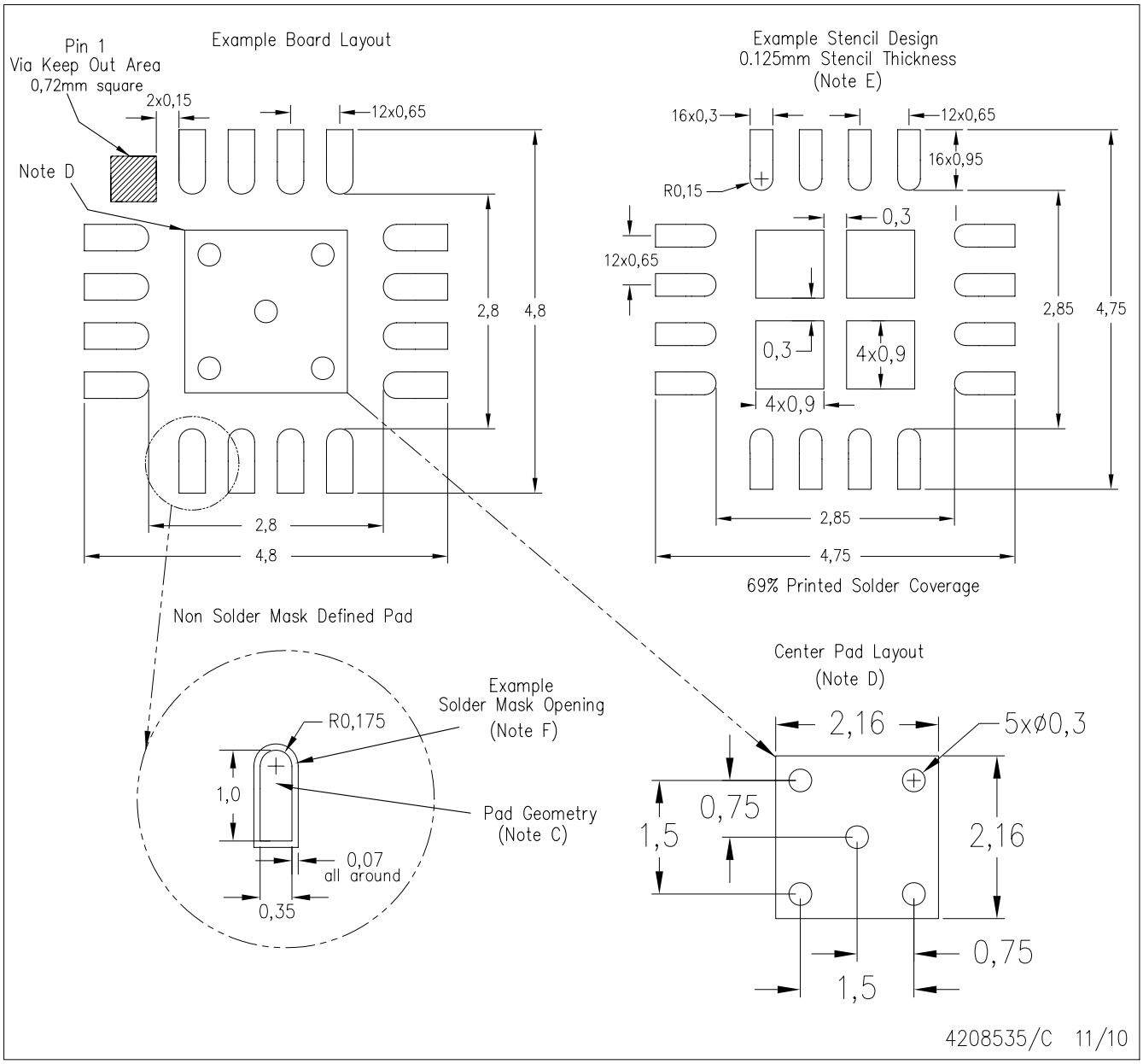
Bottom View

Exposed Thermal Pad Dimensions

4206351–2/L 05/13

NOTE: All linear dimensions are in millimeters

RGV (S–PVQFN–N16) PLASTIC QUAD FLATPACK NO–LEAD



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, QFN Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http://www.ti.com>.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
F. Customers should contact their board fabrication site for solder mask tolerances.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

2.4-GHz *Bluetooth*™ low energy and Proprietary System-on-Chip

Check for Samples: CC2541

FEATURES

- **RF**
  - **2.4-GHz *Bluetooth* low energy Compliant and Proprietary RF System-on-Chip**
  - **Supports 250-kbps, 500-kbps, 1-Mbps, 2-Mbps Data Rates**
  - **Excellent Link Budget, Enabling Long-Range Applications Without External Front End**
  - **Programmable Output Power up to 0 dBm**
  - **Excellent Receiver Sensitivity (–94 dBm at 1 Mbps), Selectivity, and Blocking Performance**
  - **Suitable for Systems Targeting Compliance With Worldwide Radio Frequency Regulations: ETSI EN 300 328 and EN 300 440 Class 2 (Europe), FCC CFR47 Part 15 (US), and ARIB STD-T66 (Japan)**
- **Layout**
  - **Few External Components**
  - **Reference Design Provided**
  - **6-mm × 6-mm QFN-40 Package**
  - **Pin-Compatible With CC2540 (When Not Using USB or I^2C)**
- **Low Power**
  - **Active-Mode RX Down to: 17.9 mA**
  - **Active-Mode TX (0 dBm): 18.2 mA**
  - **Power Mode 1 (4-µs Wake-Up): 270 µA**
  - **Power Mode 2 (Sleep Timer On): 1 µA**
  - **Power Mode 3 (External Interrupts): 0.5 µA**
  - **Wide Supply-Voltage Range (2 V–3.6 V)**
- **TPS62730 Compatible Low Power in Active Mode**
  - **RX Down to: 14.7 mA (3-V supply)**
  - **TX (0 dBm): 14.3 mA (3-V supply)**
- **Microcontroller**
  - **High-Performance and Low-Power 8051 Microcontroller Core With Code Prefetch**
  - **In-System-Programmable Flash, 128- or 256-KB**
  - **8-KB RAM With Retention in All Power Modes**
  - **Hardware Debug Support**
  - **Extensive Baseband Automation, Including Auto-Acknowledgment and Address Decoding**
  - **Retention of All Relevant Registers in All Power Modes**
- **Peripherals**
  - **Powerful Five-Channel DMA**
  - **General-Purpose Timers (One 16-Bit, Two 8-Bit)**
  - **IR Generation Circuitry**
  - **32-kHz Sleep Timer With Capture**
  - **Accurate Digital RSSI Support**
  - **Battery Monitor and Temperature Sensor**
  - **12-Bit ADC With Eight Channels and Configurable Resolution**
  - **AES Security Coprocessor**
  - **Two Powerful USARTs With Support for Several Serial Protocols**
  - **23 General-Purpose I/O Pins (21 × 4 mA, 2 × 20 mA)**
  - **I^2C interface**
  - **2 I/O Pins Have LED Driving Capabilities**
  - **Watchdog Timer**
  - **Integrated High-Performance Comparator**
- **Development Tools**
  - **CC2541 Evaluation Module Kit (CC2541EMK)**
  - **CC2541 Mini Development Kit (CC2541DK-MINI)**
  - **SmartRF™ Software**
  - **IAR Embedded Workbench™ Available**

SOFTWARE FEATURES

- ***Bluetooth*** **v4.0 Compliant Protocol Stack for Single-Mode BLE Solution**
  - **Complete Power-Optimized Stack, Including Controller and Host**
    - **GAP – Central, Peripheral, Observer, or Broadcaster (Including Combination Roles)**
    - **ATT / GATT – Client and Server**
    - **SMP – AES-128 Encryption and Decryption**
    - **L2CAP**
  - **Sample Applications and Profiles**
    - **Generic Applications for GAP Central and Peripheral Roles**
    - **Proximity, Accelerometer, Simple Keys, and Battery GATT Services**
    - **More Applications Supported in BLE Software Stack**
  - **Multiple Configuration Options**
    - **Single-Chip Configuration, Allowing Applications to Run on CC2541**
    - **Network Processor Interface for Applications Running on an External Microcontroller**
  - **BTool – Windows PC Application for Evaluation, Development, and Test**

APPLICATIONS

- **2.4-GHz** ***Bluetooth*** **low energy Systems**
- **Proprietary 2.4-GHz Systems**
- **Human-Interface Devices (Keyboard, Mouse, Remote Control)**
- **Sports and Leisure Equipment**
- **Mobile Phone Accessories**
- **Consumer Electronics**

CC2541 WITH TPS62730

- **TPS62730 is a 2-MHz Step-Down Converter With Bypass Mode**
- **Extends Battery Lifetime by up to 20%**
- **Reduced Current in All Active Modes**
- **30-nA Bypass Mode Current to Support Low-Power Modes**
- **RF Performance Unchanged**
- **Small Package Allows for Small Solution Size**
- **CC2541 Controllable**

DESCRIPTION

The CC2541 is a power-optimized true system-on-chip (SoC) solution for both *Bluetooth* low energy and proprietary 2.4-GHz applications. It enables robust network nodes to be built with low total bill-of-material costs. The CC2541 combines the excellent performance of a leading RF transceiver with an industry-standard enhanced 8051 MCU, in-system programmable flash memory, 8-KB RAM, and many other powerful supporting features and peripherals. The CC2541 is highly suited for systems where ultralow power consumption is required. This is specified by various operating modes. Short transition times between operating modes further enable low power consumption.

The CC2541 is pin-compatible with the CC2540 in the 6-mm × 6-mm QFN40 package, if the USB is not used on the CC2540 and the I^2C/extra I/O is not used on the CC2541. Compared to the CC2540, the CC2541 provides lower RF current consumption. The CC2541 does not have the USB interface of the CC2540, and provides lower maximum output power in TX mode. The CC2541 also adds a HW I^2C interface.

The CC2541 is pin-compatible with the CC2533 RF4CE-optimized IEEE 802.15.4 SoC.

The CC2541 comes in two different versions: CC2541F128/F256, with 128 KB and 256 KB of flash memory, respectively.

For the CC2541 block diagram, see Figure 1.

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

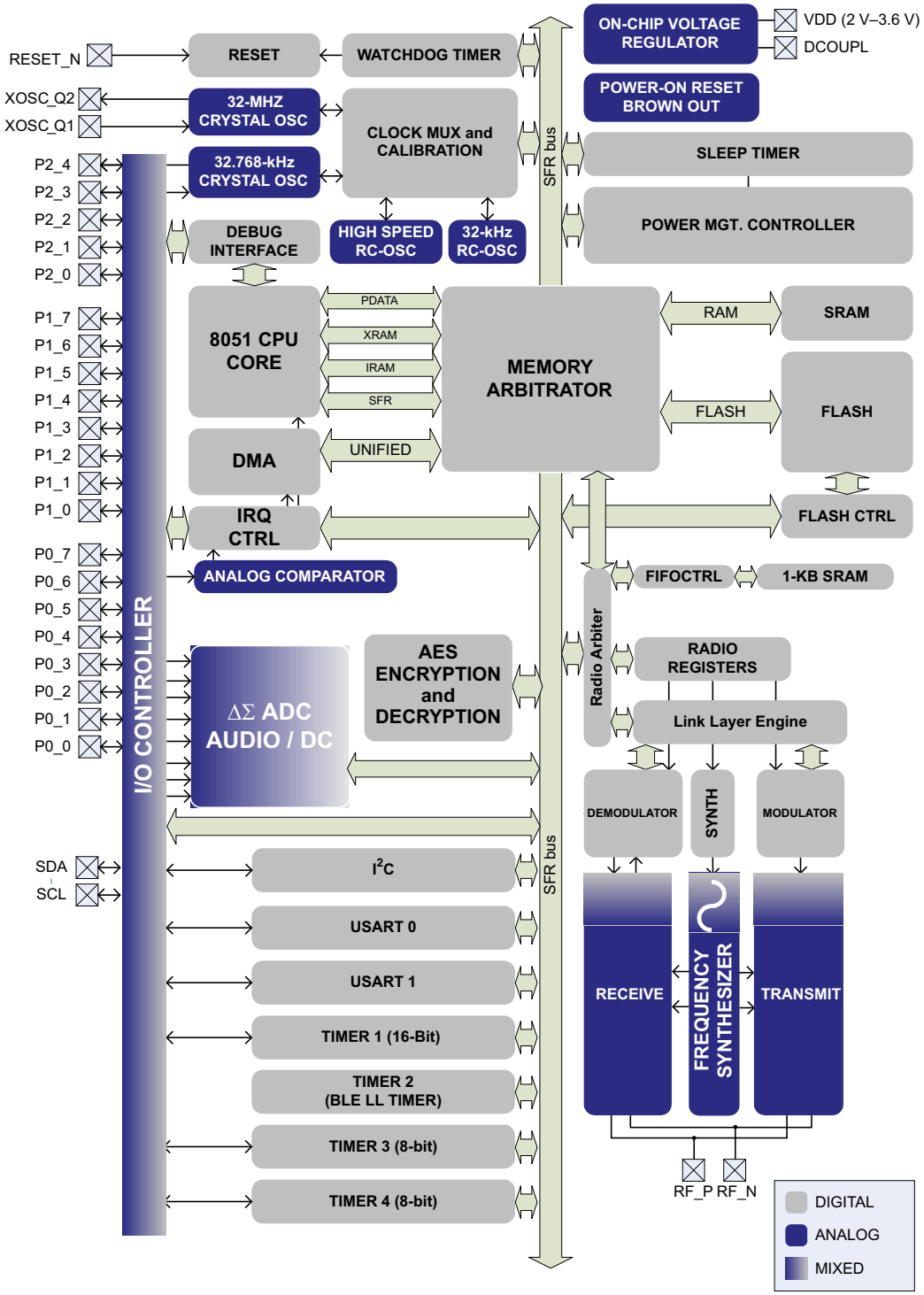


Figure 1. Block Diagram

ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Supply voltage	All supply pins must have the same voltage	–0.3	3.9	V
Voltage on any digital pin		–0.3	VDD + 0.3 ≤ 3.9	V
Input RF level			10	dBm
Storage temperature range		–40	125	°C
ESD(2)	All pins, excluding pins 25 and 26, according to human-body model, JEDEC STD 22, method A114		2	kV
	All pins, according to human-body model, JEDEC STD 22, method A114		1	kV
	According to charged-device model, JEDEC STD 22, method C101		500	V

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) **CAUTION:** ESD sesnsitive device. Precautions should be used when handling the device in order to prevent permanent damage.

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

	MIN	NOM	MAX	UNIT
Operating ambient temperature range, T_A	–40		85	°C
Operating supply voltage	2		3.6	V

ELECTRICAL CHARACTERISTICS

Measured on Texas Instruments CC2541 EM reference design with T_A = 25°C and VDD = 3 V,
1 Mbps, GFSK, 250-kHz deviation, *Bluetooth* low energy mode, and 0.1% BER

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{core}	Core current consumption	RX mode, standard mode, no peripherals active, low MCU activity		17.9		mA
		RX mode, high-gain mode, no peripherals active, low MCU activity		20.2		
		TX mode, –20 dBm output power, no peripherals active, low MCU activity		16.8		
		TX mode, 0 dBm output power, no peripherals active, low MCU activity		18.2		
		Power mode 1. Digital regulator on; 16-MHz RCOSC and 32-MHz crystal oscillator off; 32.768-kHz XOSC, POR, BOD and sleep timer active; RAM and register retention		270		µA
		Power mode 2. Digital regulator off; 16-MHz RCOSC and 32-MHz crystal oscillator off; 32.768-kHz XOSC, POR, and sleep timer active; RAM and register retention		1		
		Power mode 3. Digital regulator off; no clocks; POR active; RAM and register retention		0.5		
		Low MCU activity: 32-MHz XOSC running. No radio or peripherals. Limited flash access, no RAM access.		6.7		mA
I_{peri}	Peripheral current consumption (Adds to core current I_{core} for each peripheral unit activated)	Timer 1. Timer running, 32-MHz XOSC used		90		µA
		Timer 2. Timer running, 32-MHz XOSC used		90		
		Timer 3. Timer running, 32-MHz XOSC used		60		
		Timer 4. Timer running, 32-MHz XOSC used		70		
		Sleep timer, including 32.753-kHz RCOSC		0.6		
		ADC, when converting		1.2		mA

GENERAL CHARACTERISTICS

Measured on Texas Instruments CC2541 EM reference design with T_A = 25°C and VDD = 3 V

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
WAKE-UP AND TIMING					
Power mode 1 → Active	Digital regulator on, 16-MHz RCOSC and 32-MHz crystal oscillator off. Start-up of 16-MHz RCOSC		4		µs
Power mode 2 or 3 → Active	Digital regulator off, 16-MHz RCOSC and 32-MHz crystal oscillator off. Start-up of regulator and 16-MHz RCOSC		120		µs
Active → TX or RX	Crystal ESR = 16 Ω. Initially running on 16-MHz RCOSC, with 32-MHz XOSC OFF		500		µs
	With 32-MHz XOSC initially on		180		µs
RX/TX turnaround	Proprietary auto mode		130		µs
	BLE mode		150		
RADIO PART					
RF frequency range	Programmable in 1-MHz steps	2379		2496	MHz
Data rate and modulation format	2 Mbps, GFSK, 500-kHz deviation 2 Mbps, GFSK, 320-kHz deviation 1 Mbps, GFSK, 250-kHz deviation 1 Mbps, GFSK, 160-kHz deviation 500 kbps, MSK 250 kbps, GFSK, 160-kHz deviation 250 kbps, MSK				

RF RECEIVE SECTION

Measured on Texas Instruments CC2541 EM reference design with T_A = 25°C, VDD = 3 V, f_c = 2440 MHz

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
2 Mbps, GFSK, 500-kHz Deviation, 0.1% BER					
Receiver sensitivity			–90		dBm
Saturation	BER < 0.1%		–1		dBm
Co-channel rejection	Wanted signal at –67 dBm		–9		dB
In-band blocking rejection	±2 MHz offset, 0.1% BER, wanted signal –67 dBm		–2		dB
	±4 MHz offset, 0.1% BER, wanted signal –67 dBm		36		
	±6 MHz or greater offset, 0.1% BER, wanted signal –67 dBm		41		
Frequency error tolerance(1)	Including both initial tolerance and drift. Sensitivity better than –67dBm, 250 byte payload. BER 0.1%	–300		300	kHz
Symbol rate error tolerance(2)	Maximum packet length. Sensitivity better than–67dBm, 250 byte payload. BER 0.1%	–120		120	ppm
2 Mbps, GFSK, 320-kHz Deviation, 0.1% BER					
Receiver sensitivity			–86		dBm
Saturation	BER < 0.1%		–7		dBm
Co-channel rejection	Wanted signal at –67 dBm		–12		dB
In-band blocking rejection	±2 MHz offset, 0.1% BER, wanted signal –67 dBm		–1		dB
	±4 MHz offset, 0.1% BER, wanted signal –67 dBm		34		
	±6 MHz or greater offset, 0.1% BER, wanted signal –67 dBm		39		
Frequency error tolerance(1)	Including both initial tolerance and drift. Sensitivity better than –67 dBm, 250 byte payload. BER 0.1%	–300		300	kHz
Symbol rate error tolerance(2)	Maximum packet length. Sensitivity better than –67 dBm, 250 byte payload. BER 0.1%	–120		120	ppm

(1) Difference between center frequency of the received RF signal and local oscillator frequency
(2) Difference between incoming symbol rate and the internally generated symbol rate

RF RECEIVE SECTION (continued)

Measured on Texas Instruments CC2541 EM reference design with T_A = 25°C, VDD = 3 V, f_c = 2440 MHz

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
1 Mbps, GFSK, 250-kHz Deviation, *Bluetooth* low energy Mode, 0.1% BER					
Receiver sensitivity(3)(4)	High-gain mode		–94		dBm
	Standard mode		–88		
Saturation(4)	BER < 0.1%		5		dBm
Co-channel rejection(4)	Wanted signal –67 dBm		–6		dB
In-band blocking rejection(4)	±1 MHz offset, 0.1% BER, wanted signal –67 dBm		–2		dB
	±2 MHz offset, 0.1% BER, wanted signal –67 dBm		26		
	±3 MHz offset, 0.1% BER, wanted signal –67 dBm		34		
	>6 MHz offset, 0.1% BER, wanted signal –67 dBm		33		
Out-of-band blocking rejection(4)	Minimum interferer level < 2 GHz (Wanted signal –67 dBm)		–21		dBm
	Minimum interferer level [2 GHz, 3 GHz] (Wanted signal –67 dBm)		–25		
	Minimum interferer level > 3 GHz (Wanted signal –67 dBm)		–7		
Intermodulation(4)	Minimum interferer level		–36		dBm
Frequency error tolerance(5)	Including both initial tolerance and drift. Sensitivity better than -67dBm, 250 byte payload. BER 0.1%	–250		250	kHz
Symbol rate error tolerance(6)	Maximum packet length. Sensitivity better than –67 dBm, 250 byte payload. BER 0.1%	–80		80	ppm
1 Mbps, GFSK, 160-kHz Deviation, 0.1% BER					
Receiver sensitivity(7)			–91		dBm
Saturation	BER < 0.1%		0		dBm
Co-channel rejection	Wanted signal 10 dB above sensitivity level		–9		dB
In-band blocking rejection	±1-MHz offset, 0.1% BER, wanted signal –67 dBm		2		dB
	±2-MHz offset, 0.1% BER, wanted signal –67 dBm		24		
	±3-MHz offset, 0.1% BER, wanted signal -–67 dBm		27		
	>6-MHz offset, 0.1% BER, wanted signal –67 dBm		32		
Frequency error tolerance(5)	Including both initial tolerance and drift. Sensitivity better than –67 dBm, 250-byte payload. BER 0.1%	–200		200	kHz
Symbol rate error tolerance(6)	Maximum packet length. Sensitivity better than –67 dBm, 250-byte payload. BER 0.1%	–80		80	ppm
500 kbps, MSK, 0.1% BER					
Receiver sensitivity(7)			–99		dBm
Saturation	BER < 0.1%		0		dBm
Co-channel rejection	Wanted signal –67 dBm		–5		dB
In-band blocking rejection	±1-MHz offset, 0.1% BER, wanted signal –67 dBm		20		dB
	±2-MHz offset, 0.1% BER, wanted signal –67 dBm		27		
	>2-MHz offset, 0.1% BER, wanted signal –67 dBm		28		
Frequency error tolerance	Including both initial tolerance and drift. Sensitivity better than –67 dBm, 250-byte payload. BER 0.1%	–150		150	kHz
Symbol rate error tolerance	Maximum packet length. Sensitivity better than –67 dBm, 250-byte payload. BER 0.1%	–80		80	ppm

(3) The receiver sensitivity setting is programmable using a TI BLE stack vendor-specific API command. The default value is standard mode.
(4) Results based on standard-gain mode.
(5) Difference between center frequency of the received RF signal and local oscillator frequency
(6) Difference between incoming symbol rate and the internally generated symbol rate
(7) Results based on high-gain mode.

RF RECEIVE SECTION (continued)

Measured on Texas Instruments CC2541 EM reference design with T_A = 25°C, VDD = 3 V, f_c = 2440 MHz

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
250 kbps, GFSK, 160 kHz Deviation, 0.1% BER					
Receiver sensitivity (8)			–98		dBm
Saturation	BER < 0.1%		0		dBm
Co-channel rejection	Wanted signal -67 dBm		–3		dB
In-band blocking rejection	±1-MHz offset, 0.1% BER, wanted signal –67 dBm		23		dB
	±2-MHz offset, 0.1% BER, wanted signal –67 dBm		28		
	>2-MHz offset, 0.1% BER, wanted signal –67 dBm		29		
Frequency error tolerance (9)	Including both initial tolerance and drift. Sensitivity better than –67 dBm, 250-byte payload. BER 0.1%	–150		150	kHz
Symbol rate error tolerance (10)	Maximum packet length. Sensitivity better than –67 dBm, 250-byte payload. BER 0.1%	–80		80	ppm
250 kbps, MSK, 0.1% BER					
Receiver sensitivity (11)			–99		dBm
Saturation	BER < 0.1%		0		dBm
Co-channel rejection	Wanted signal -67 dBm		–5		dB
In-band blocking rejection	±1-MHz offset, 0.1% BER, wanted signal –67 dBm		20		dB
	±2-MHz offset, 0.1% BER, wanted signal –67 dBm		29		
	>2-MHz offset, 0.1% BER, wanted signal –67 dBm		30		
Frequency error tolerance	Including both initial tolerance and drift. Sensitivity better than –67 dBm, 250-byte payload. BER 0.1%	–150		150	kHz
Symbol rate error tolerance	Maximum packet length. Sensitivity better than –67 dBm, 250-byte payload. BER 0.1%	–80		80	ppm
ALL RATES/FORMATS					
Spurious emission in RX. Conducted measurement	f < 1 GHz		–67		dBm
Spurious emission in RX. Conducted measurement	f > 1 GHz		–57		dBm

(8) Results based on standard-gain mode.
(9) Difference between center frequency of the received RF signal and local oscillator frequency
(10) Difference between incoming symbol rate and the internally generated symbol rate
(11) Results based on high-gain mode.

RF TRANSMIT SECTION

Measured on Texas Instruments CC2541 EM reference design with T_A = 25°C, VDD = 3 V and f_c = 2440 MHz

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Output power	Delivered to a single-ended 50-Ω load through a balun using maximum recommended output power setting		0		dBm
	Delivered to a single-ended 50-Ω load through a balun using minimum recommended output power setting		–23		
Programmable output power range	Delivered to a single-ended 50-Ω load through a balun using minimum recommended output power setting		23		dB
Spurious emission conducted measurement	f < 1 GHz		–52		dBm
	f > 1 GHz		–48		dBm
	Suitable for systems targeting compliance with worldwide radio-frequency regulations ETSI EN 300 328 and EN 300 440 Class 2 (Europe), FCC CFR47 Part 15 (US), and ARIB STD-T66 (Japan)				
Optimum load impedance	Differential impedance as seen from the RF port (RF_P and RF_N) toward the antenna		70 +j30		Ω

Designs with antenna connectors that require conducted ETSI compliance at 64 MHz should insert an LC resonator in front of the antenna connector. Use a 1.6-nH inductor in parallel with a 1.8-pF capacitor. Connect both from the signal trace to a good RF ground.

CURRENT CONSUMPTION WITH TPS62730

Measured on Texas Instruments CC2541 TPA62730 EM reference design with T_A = 25°C, VDD = 3 V and f_c = 2440 MHz,
1 Mbsp, GFSK, 250-kHz deviation, Bluetooth™ low energy Mode, 1% BER(1)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Current consumption	RX mode, standard mode, no peripherals active, low MCU activity, MCU at 1 MHz		14.7		mA
	RX mode, high-gain mode, no peripherals active, low MCU activity, MCU at 1 MHz		16.7		
	TX mode, –20 dBm output power, no peripherals active, low MCU activity, MCU at 1 MHz		13.1		
	TX mode, 0 dBm output power, no peripherals active, low MCU activity, MCU at 1 MHz		14.3		

(1) 0.1% BER maps to 30.8% PER

32-MHz CRYSTAL OSCILLATOR

Measured on Texas Instruments CC2541 EM reference design with T_A = 25°C and VDD = 3 V

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
	Crystal frequency			32		MHz
	Crystal frequency accuracy requirement(1)		–40		40	ppm
ESR	Equivalent series resistance		6		60	Ω
C_0	Crystal shunt capacitance		1		7	pF
C_L	Crystal load capacitance		10		16	pF
	Start-up time			0.25		ms
	Power-down guard time	The crystal oscillator must be in power down for a guard time before it is used again. This requirement is valid for all modes of operation. The need for power-down guard time can vary with crystal type and load.	3			ms

(1) Including aging and temperature dependency, as specified by [1]

32.768-kHz CRYSTAL OSCILLATOR

Measured on Texas Instruments CC2541 EM reference design with T_A = 25°C and VDD = 3 V

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
	Crystal frequency			32.768		kHz
	Crystal frequency accuracy requirement(1)		–40		40	ppm
ESR	Equivalent series resistance			40	130	kΩ
C_0	Crystal shunt capacitance			0.9	2	pF
C_L	Crystal load capacitance			12	16	pF
	Start-up time			0.4		s

(1) Including aging and temperature dependency, as specified by [1]

32-kHz RC OSCILLATOR

Measured on Texas Instruments CC2541 EM reference design with T_A = 25°C and VDD = 3 V.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Calibrated frequency(1)			32.753		kHz
Frequency accuracy after calibration			±0.2%		
Temperature coefficient(2)			0.4		%/°C
Supply-voltage coefficient(3)			3		%/V
Calibration time(4)			2		ms

(1) The calibrated 32-kHz RC oscillator frequency is the 32-MHz XTAL frequency divided by 977.
(2) Frequency drift when temperature changes after calibration
(3) Frequency drift when supply voltage changes after calibration
(4) When the 32-kHz RC oscillator is enabled, it is calibrated when a switch from the 16-MHz RC oscillator to the 32-MHz crystal oscillator is performed while SLEEPCMD.OSC32K_CALDIS is set to 0.

16-MHz RC OSCILLATOR

Measured on Texas Instruments CC2541 EM reference design with T_A = 25°C and VDD = 3 V

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Frequency(1)			16		MHz
Uncalibrated frequency accuracy			±18%		
Calibrated frequency accuracy			±0.6%		
Start-up time			10		µs
Initial calibration time(2)			50		µs

(1) The calibrated 16-MHz RC oscillator frequency is the 32-MHz XTAL frequency divided by 2.
(2) When the 16-MHz RC oscillator is enabled, it is calibrated when a switch from the 16-MHz RC oscillator to the 32-MHz crystal oscillator is performed while SLEEPCMD.OSC_PD is set to 0.

RSSI CHARACTERISTICS

Measured on Texas Instruments CC2541 EM reference design with T_A = 25°C and VDD = 3 V

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
2 Mbps, GFSK, 320-kHz Deviation, 0.1% BER and 2 Mbps, GFSK, 500-kHz Deviation, 0.1% BER					
Useful RSSI range(1)	Reduced gain by AGC algorithm		64		dB
	High gain by AGC algorithm		64		
RSSI offset(1)	Reduced gain by AGC algorithm		79		dBm
	High gain by AGC algorithm		99		
Absolute uncalibrated accuracy(1)			±6		dB
Step size (LSB value)			1		dB
All Other Rates/Formats					
Useful RSSI range(1)	Standard mode		64		dB
	High-gain mode		64		
RSSI offset(1)	Standard mode		98		dBm
	High-gain mode		107		
Absolute uncalibrated accuracy(1)			±3		dB
Step size (LSB value)			1		dB

(1) Assuming CC2541 EM reference design. Other RF designs give an offset from the reported value.

FREQUENCY SYNTHESIZER CHARACTERISTICS

Measured on Texas Instruments CC2541 EM reference design with T_A = 25°C, VDD = 3 V and f_c = 2440 MHz

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Phase noise, unmodulated carrier	At ±1-MHz offset from carrier		–109		dBc/Hz
	At ±3-MHz offset from carrier		–112		
	At ±5-MHz offset from carrier		–119		

ANALOG TEMPERATURE SENSOR

Measured on Texas Instruments CC2541 EM reference design with T_A = 25°C and VDD = 3 V

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Output	Measured using integrated ADC, internal band-gap voltage reference, and maximum resolution		1480		12-bit
Temperature coefficient			4.5		/ 1°C
Voltage coefficient			1		0.1 V
Initial accuracy without calibration			±10		°C
Accuracy using 1-point calibration			±5		°C
Current consumption when enabled			0.5		mA

COMPARATOR CHARACTERISTICS

T_A = 25°C, VDD = 3 V. All measurement results are obtained using the CC2541 reference designs, post-calibration.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Common-mode maximum voltage			VDD		V
Common-mode minimum voltage			–0.3		
Input offset voltage			1		mV
Offset vs temperature			16		µV/°C
Offset vs operating voltage			4		mV/V
Supply current			230		nA
Hysteresis			0.15		mV

ADC CHARACTERISTICS

T_A = 25°C and VDD = 3 V

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
	Input voltage	VDD is voltage on AVDD5 pin	0		VDD	V
	External reference voltage	VDD is voltage on AVDD5 pin	0		VDD	V
	External reference voltage differential	VDD is voltage on AVDD5 pin	0		VDD	V
	Input resistance, signal	Simulated using 4-MHz clock speed		197		kΩ
	Full-scale signal(1)	Peak-to-peak, defines 0 dBFS		2.97		V
ENOB(1)	Effective number of bits	Single-ended input, 7-bit setting		5.7		bits
		Single-ended input, 9-bit setting		7.5		
		Single-ended input, 10-bit setting		9.3		
		Single-ended input, 12-bit setting		10.3		
		Differential input, 7-bit setting		6.5		
		Differential input, 9-bit setting		8.3		
		Differential input, 10-bit setting		10		
		Differential input, 12-bit setting		11.5		
		10-bit setting, clocked by RCOSC		9.7		
		12-bit setting, clocked by RCOSC		10.9		
	Useful power bandwidth	7-bit setting, both single and differential		0–20		kHz
THD	Total harmonic distortion	Single ended input, 12-bit setting, –6 dBFS(1)		–75.2		dB
		Differential input, 12-bit setting, –6 dBFS(1)		–86.6		
	Signal to nonharmonic ratio	Single-ended input, 12-bit setting(1)		70.2		dB
		Differential input, 12-bit setting(1)		79.3		
		Single-ended input, 12-bit setting, –6 dBFS(1)		78.8		
		Differential input, 12-bit setting, –6 dBFS(1)		88.9		
CMRR	Common-mode rejection ratio	Differential input, 12-bit setting, 1-kHz sine (0 dBFS), limited by ADC resolution		>84		dB
	Crosstalk	Single ended input, 12-bit setting, 1-kHz sine (0 dBFS), limited by ADC resolution		>84		dB
	Offset	Midscale		–3		mV
	Gain error			0.68%		
DNL	Differential nonlinearity	12-bit setting, mean(1)		0.05		LSB
		12-bit setting, maximum(1)		0.9		
INL	Integral nonlinearity	12-bit setting, mean(1)		4.6		LSB
		12-bit setting, maximum(1)		13.3		
		12-bit setting, mean, clocked by RCOSC		10		
		12-bit setting, max, clocked by RCOSC		29		
SINAD (–THD+N)	Signal-to-noise-and-distortion	Single ended input, 7-bit setting(1)		35.4		dB
		Single ended input, 9-bit setting(1)		46.8		
		Single ended input, 10-bit setting(1)		57.5		
		Single ended input, 12-bit setting(1)		66.6		
		Differential input, 7-bit setting(1)		40.7		
		Differential input, 9-bit setting(1)		51.6		
		Differential input, 10-bit setting(1)		61.8		
		Differential input, 12-bit setting(1)		70.8		
	Conversion time	7-bit setting		20		µs
		9-bit setting		36		
		10-bit setting		68		
		12-bit setting		132		

(1) Measured with 300-Hz sine-wave input and VDD as reference.

ADC CHARACTERISTICS (continued)

T_A = 25°C and VDD = 3 V

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Power consumption			1.2		mA
Internal reference VDD coefficient			4		mV/V
Internal reference temperature coefficient			0.4		mV/10°C
Internal reference voltage			1.24		V

CONTROL INPUT AC CHARACTERISTICS

T_A = –40°C to 85°C, VDD = 2 V to 3.6 V

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
System clock, f_{SYSCLK} $t_{SYSCLK} = 1/ f_{SYSCLK}$	The undivided system clock is 32 MHz when crystal oscillator is used. The undivided system clock is 16 MHz when calibrated 16-MHz RC oscillator is used.	16		32	MHz
RESET_N low duration	See item 1, Figure 2. This is the shortest pulse that is recognized as a complete reset pin request. Note that shorter pulses may be recognized but do not lead to complete reset of all modules within the chip.	1			µs
Interrupt pulse duration	See item 2, Figure 2.This is the shortest pulse that is recognized as an interrupt request.	20			ns

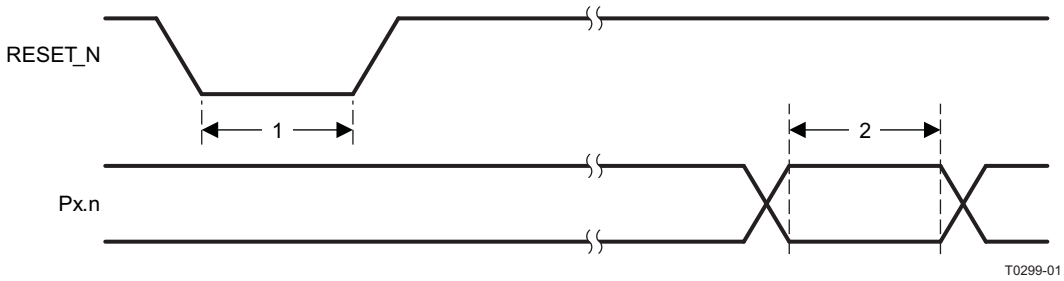


Figure 2. Control Input AC Characteristics

SPI AC CHARACTERISTICS

T_A = –40°C to 85°C, VDD = 2 V to 3.6 V

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_1	SCK period	Master, RX and TX	250			ns
		Slave, RX and TX	250			
	SCK duty cycle	Master		50%		
t_2	SSN low to SCK	Master	63			ns
		Slave	63			
t_3	SCK to SSN high	Master	63			ns
		Slave	63			
t_4	MOSI early out	Master, load = 10 pF			7	ns
t_5	MOSI late out	Master, load = 10 pF			10	ns
t_6	MISO setup	Master	90			ns
t_7	MISO hold	Master	10			ns
	SCK duty cycle	Slave		50%		ns
t_{10}	MOSI setup	Slave	35			ns
t_{11}	MOSI hold	Slave	10			ns
t_9	MISO late out	Slave, load = 10 pF			95	ns
	Operating frequency	Master, TX only			8	MHz
		Master, RX and TX			4	
		Slave, RX only			8	
		Slave, RX and TX			4	

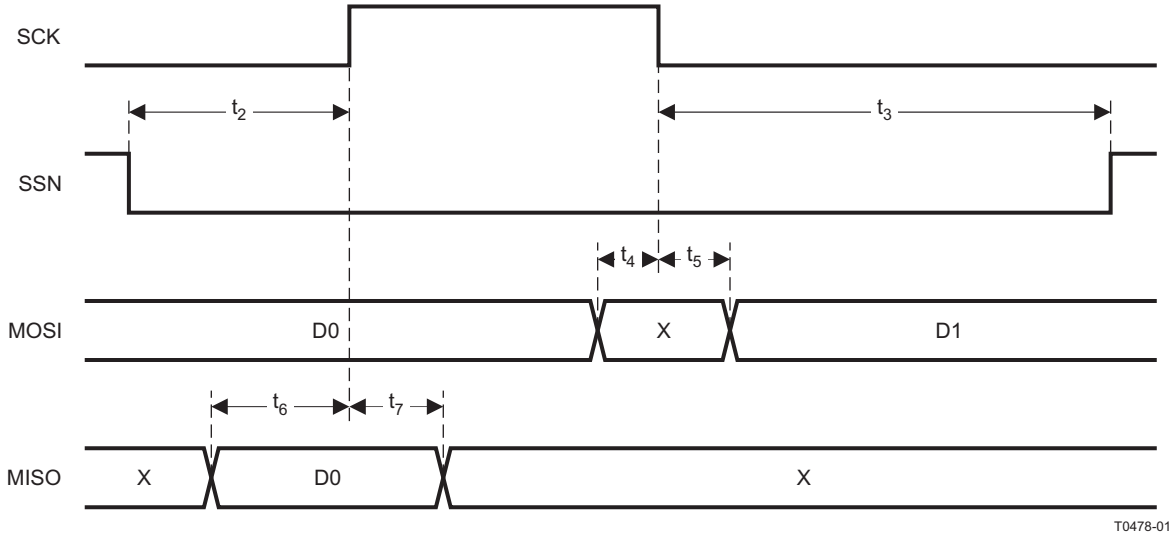


Figure 3. SPI Master AC Characteristics

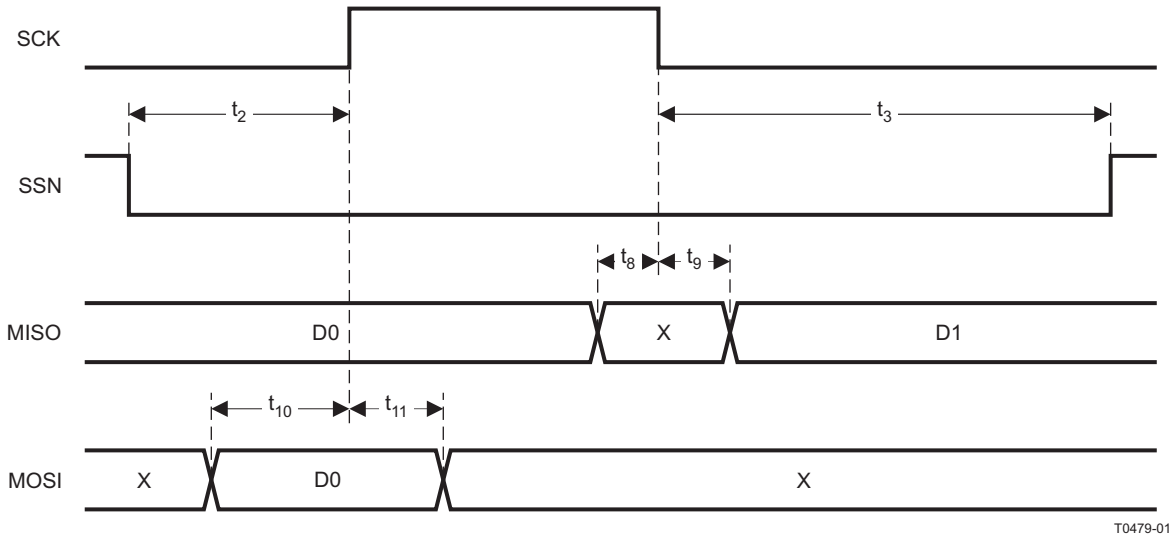


Figure 4. SPI Slave AC Characteristics

DEBUG INTERFACE AC CHARACTERISTICS

T_A = –40°C to 85°C, VDD = 2 V to 3.6 V

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{clk_dbg}	Debug clock frequency (see Figure 5)				12	MHz
t_1	Allowed high pulse on clock (see Figure 5)		35			ns
t_2	Allowed low pulse on clock (see Figure 5)		35			ns
t_3	EXT_RESET_N low to first falling edge on debug clock (see Figure 7)		167			ns
t_4	Falling edge on clock to EXT_RESET_N high (see Figure 7)		83			ns
t_5	EXT_RESET_N high to first debug command (see Figure 7)		83			ns
t_6	Debug data setup (see Figure 6)		2			ns
t_7	Debug data hold (see Figure 6)		4			ns
t_8	Clock-to-data delay (see Figure 6)	Load = 10 pF			30	ns

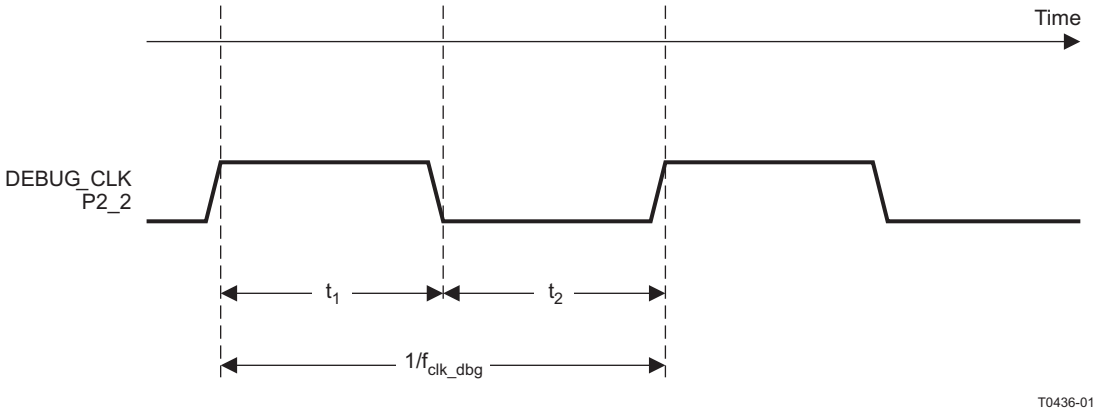


Figure 5. Debug Clock – Basic Timing

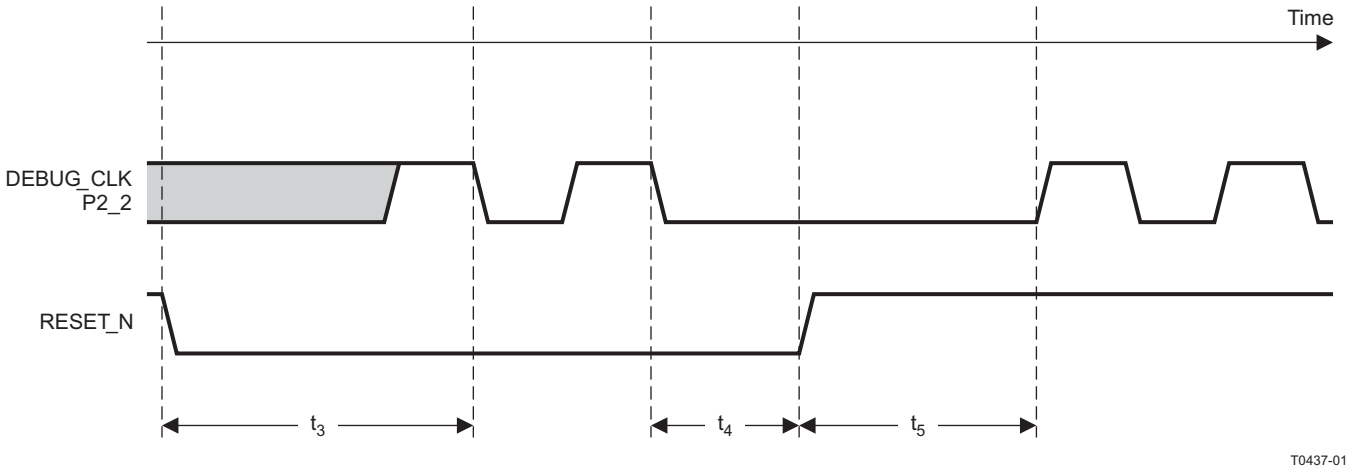


Figure 6. Debug Enable Timing

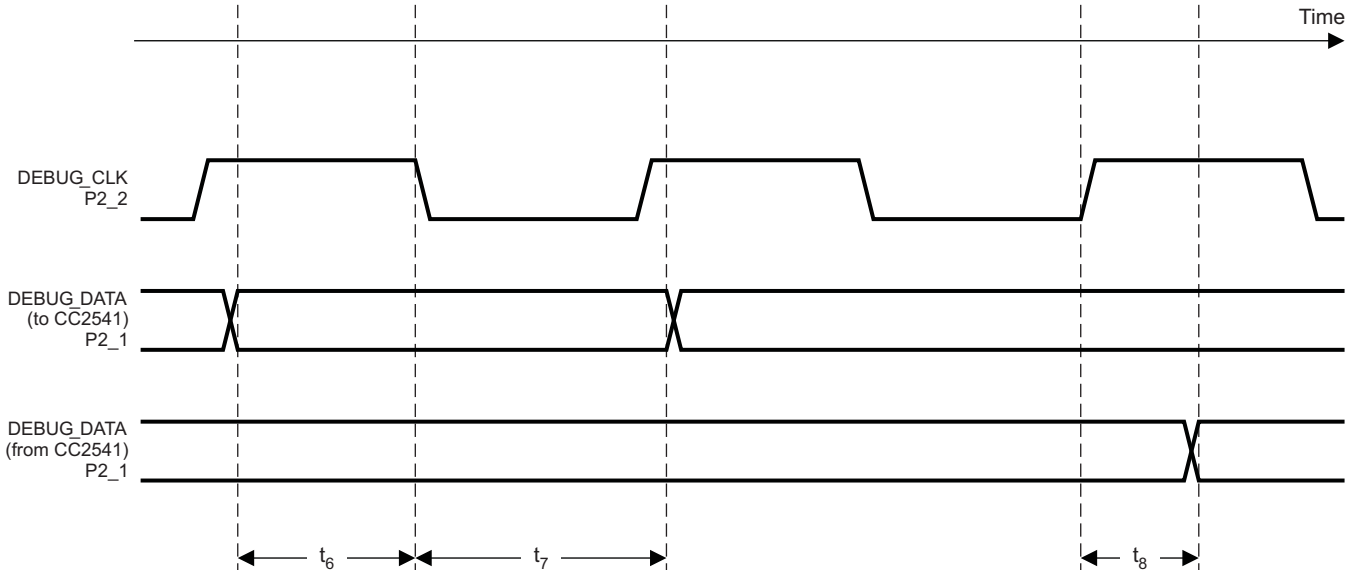


Figure 7. Data Setup and Hold Timing

TIMER INPUTS AC CHARACTERISTICS

T_A = –40°C to 85°C, VDD = 2 V to 3.6 V

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Input capture pulse duration	Synchronizers determine the shortest input pulse that can be recognized. The synchronizers operate at the current system clock rate (16 MHz or 32 MHz).	1.5			t_{SYSCLK}

DC CHARACTERISTICS

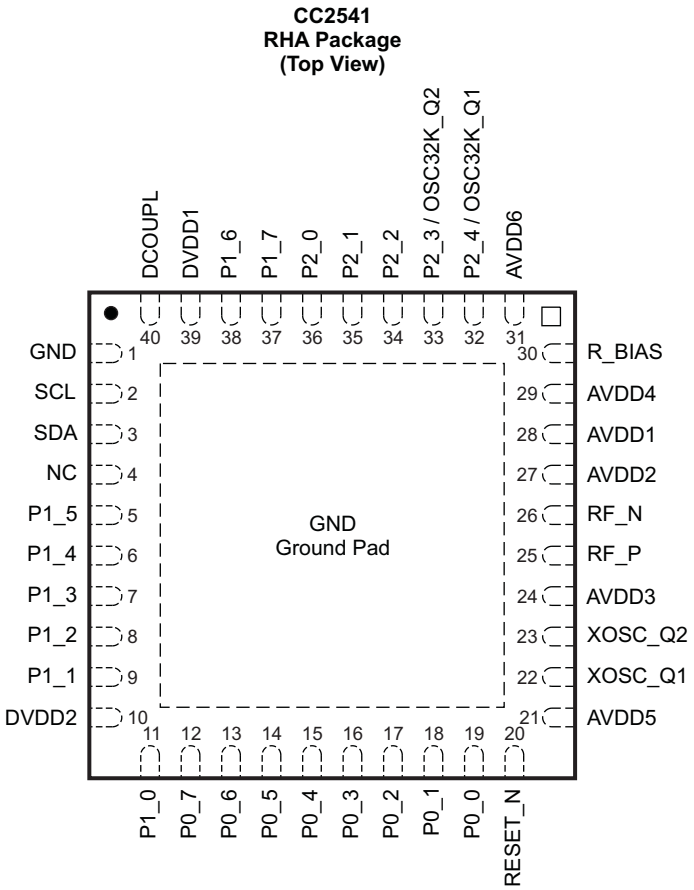
T_A = 25°C, VDD = 3 V

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Logic-0 input voltage				0.5	V
Logic-1 input voltage		2.4			V
Logic-0 input current	Input equals 0 V	–50		50	nA
Logic-1 input current	Input equals VDD	–50		50	nA
I/O-pin pullup and pulldown resistors			20		kΩ
Logic-0 output voltage, 4- mA pins	Output load 4 mA			0.5	V
Logic-1 output voltage, 4-mA pins	Output load 4 mA	2.5			V
Logic-0 output voltage, 20- mA pins	Output load 20 mA			0.5	V
Logic-1 output voltage, 20-mA pins	Output load 20 mA	2.5			V

DEVICE INFORMATION

PIN DESCRIPTIONS

The CC2541 pinout is shown in Figure 8 and a short description of the pins follows.



NOTE: The exposed ground pad must be connected to a solid ground plane, as this is the ground connection for the chip.

Figure 8. Pinout Top View

PIN DESCRIPTIONS

PIN NAME	PIN	PIN TYPE	DESCRIPTION
AVDD1	28	Power (analog)	2-V–3.6-V analog power-supply connection
AVDD2	27	Power (analog)	2-V–3.6-V analog power-supply connection
AVDD3	24	Power (analog)	2-V–3.6-V analog power-supply connection
AVDD4	29	Power (analog)	2-V–3.6-V analog power-supply connection
AVDD5	21	Power (analog)	2-V–3.6-V analog power-supply connection
AVDD6	31	Power (analog)	2-V–3.6-V analog power-supply connection
DCOUPL	40	Power (digital)	1.8-V digital power-supply decoupling. Do not use for supplying external circuits.
DVDD1	39	Power (digital)	2-V–3.6-V digital power-supply connection
DVDD2	10	Power (digital)	2-V–3.6-V digital power-supply connection
GND	1	Ground pin	Connect to GND
GND	—	Ground	The ground pad must be connected to a solid ground plane.
NC	4	Unused pins	Not connected
P0_0	19	Digital I/O	Port 0.0
P0_1	18	Digital I/O	Port 0.1
P0_2	17	Digital I/O	Port 0.2
P0_3	16	Digital I/O	Port 0.3
P0_4	15	Digital I/O	Port 0.4
P0_5	14	Digital I/O	Port 0.5
P0_6	13	Digital I/O	Port 0.6
P0_7	12	Digital I/O	Port 0.7
P1_0	11	Digital I/O	Port 1.0 – 20-mA drive capability
P1_1	9	Digital I/O	Port 1.1 – 20-mA drive capability
P1_2	8	Digital I/O	Port 1.2
P1_3	7	Digital I/O	Port 1.3
P1_4	6	Digital I/O	Port 1.4
P1_5	5	Digital I/O	Port 1.5
P1_6	38	Digital I/O	Port 1.6
P1_7	37	Digital I/O	Port 1.7
P2_0	36	Digital I/O	Port 2.0
P2_1/DD	35	Digital I/O	Port 2.1 / debug data
P2_2/DC	34	Digital I/O	Port 2.2 / debug clock
P2_3/ OSC32K_Q2	33	Digital I/O, Analog I/O	Port 2.3/32.768 kHz XOSC
P2_4/ OSC32K_Q1	32	Digital I/O, Analog I/O	Port 2.4/32.768 kHz XOSC
RBIAS	30	Analog I/O	External precision bias resistor for reference current
RESET_N	20	Digital input	Reset, active-low
RF_N	26	RF I/O	Negative RF input signal to LNA during RX Negative RF output signal from PA during TX
RF_P	25	RF I/O	Positive RF input signal to LNA during RX Positive RF output signal from PA during TX
SCL	2	I^2C clock or digital I/O	Can be used as I^2C clock pin or digital I/O. Leave floating if not used. If grounded disable pull up
SDA	3	I^2C clock or digital I/O	Can be used as I^2C data pin or digital I/O. Leave floating if not used. If grounded disable pull up
XOSC_Q1	22	Analog I/O	32-MHz crystal oscillator pin 1 or external clock input
XOSC_Q2	23	Analog I/O	32-MHz crystal oscillator pin 2

BLOCK DIAGRAM

A block diagram of the CC2541 is shown in Figure 9. The modules can be roughly divided into one of three categories: CPU-related modules; modules related to power, test, and clock distribution; and radio-related modules. In the following subsections, a short description of each module is given.

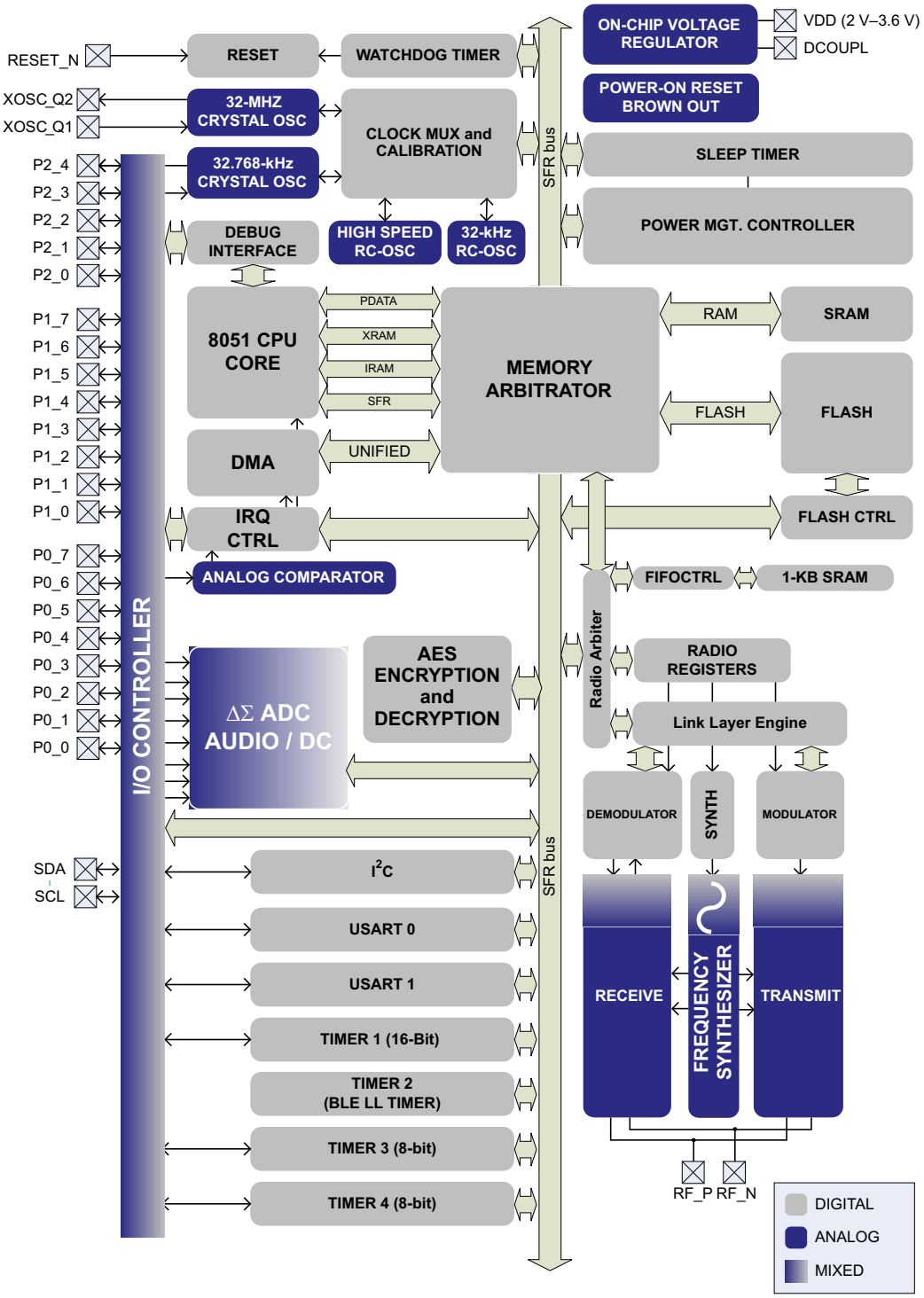


Figure 9. CC2541 Block Diagram

BLOCK DESCRIPTIONS

A block diagram of the CC2541 is shown in Figure 9. The modules can be roughly divided into one of three categories: CPU-related modules; modules related to power, test, and clock distribution; and radio-related modules. In the following subsections, a short description of each module is given.

CPU and Memory

The **8051 CPU core** is a single-cycle 8051-compatible core. It has three different memory access busses (SFR, DATA, and CODE/XDATA), a debug interface, and an 18-input extended interrupt unit.

The **memory arbiter** is at the heart of the system, as it connects the CPU and DMA controller with the physical memories and all peripherals through the SFR bus. The memory arbiter has four memory-access points, access of which can map to one of three physical memories: an SRAM, flash memory, and XREG/SFR registers. It is responsible for performing arbitration and sequencing between simultaneous memory accesses to the same physical memory.

The **SFR bus** is drawn conceptually in Figure 9 as a common bus that connects all hardware peripherals to the memory arbiter. The SFR bus in the block diagram also provides access to the radio registers in the radio register bank, even though these are indeed mapped into XDATA memory space.

The **8-KB SRAM** maps to the DATA memory space and to parts of the XDATA memory spaces. The SRAM is an ultralow-power SRAM that retains its contents even when the digital part is powered off (power mode 2 and mode 3).

The **128/256 KB flash block** provides in-circuit programmable non-volatile program memory for the device, and maps into the CODE and XDATA memory spaces.

Peripherals

Writing to the flash block is performed through a **flash controller** that allows page-wise erasure and 4-bytewise programming. See User Guide for details on the flash controller.

A versatile five-channel **DMA controller** is available in the system, accesses memory using the XDATA memory space, and thus has access to all physical memories. Each channel (trigger, priority, transfer mode, addressing mode, source and destination pointers, and transfer count) is configured with DMA descriptors that can be located anywhere in memory. Many of the hardware peripherals (AES core, flash controller, USARTs, timers, ADC interface, etc.) can be used with the DMA controller for efficient operation by performing data transfers between a single SFR or XREG address and flash/SRAM.

Each CC2541 contains a unique 48-bit IEEE address that can be used as the public device address for a *Bluetooth* device. Designers are free to use this address, or provide their own, as described in the *Bluetooth* specfication.

The **interrupt controller** services a total of 18 interrupt sources, divided into six interrupt groups, each of which is associated with one of four interrupt priorities. I/O and sleep timer interrupt requests are serviced even if the device is in a sleep mode (power modes 1 and 2) by bringing the CC2541 back to the active mode.

The **debug interface** implements a proprietary two-wire serial interface that is used for in-circuit debugging. Through this debug interface, it is possible to erase or program the entire flash memory, control which oscillators are enabled, stop and start execution of the user program, execute instructions on the 8051 core, set code breakpoints, and single-step through instructions in the code. Using these techniques, it is possible to perform in-circuit debugging and external flash programming elegantly.

The **I/O controller** is responsible for all general-purpose I/O pins. The CPU can configure whether peripheral modules control certain pins or whether they are under software control, and if so, whether each pin is configured as an input or output and if a pullup or pulldown resistor in the pad is connected. Each peripheral that connects to the I/O pins can choose between two different I/O pin locations to ensure flexibility in various applications.

The **sleep timer** is an ultralow-power timer that can either use an external 32.768-kHz crystal oscillator or an internal 32.753-kHz RC oscillator. The sleep timer runs continuously in all operating modes except power mode 3. Typical applications of this timer are as a real-time counter or as a wake-up timer to get out of power mode 1 or mode 2.

A built-in **watchdog timer** allows the CC2541 to reset itself if the firmware hangs. When enabled by software, the watchdog timer must be cleared periodically; otherwise, it resets the device when it times out.

Timer 1 is a 16-bit timer with timer/counter/PWM functionality. It has a programmable prescaler, a 16-bit period value, and five individually programmable counter/capture channels, each with a 16-bit compare value. Each of the counter/capture channels can be used as a PWM output or to capture the timing of edges on input signals. It can also be configured in IR generation mode, where it counts timer 3 periods and the output is ANDed with the output of timer 3 to generate modulated consumer IR signals with minimal CPU interaction.

Timer 2 is a 40-bit timer. It has a 16-bit counter with a configurable timer period and a 24-bit overflow counter that can be used to keep track of the number of periods that have transpired. A 40-bit capture register is also used to record the exact time at which a start-of-frame delimiter is received/transmitted or the exact time at which transmission ends. There are two 16-bit output compare registers and two 24-bit overflow compare registers that can be used to give exact timing for start of RX or TX to the radio or general interrupts.

Timer 3 and timer 4 are 8-bit timers with timer/counter/PWM functionality. They have a programmable prescaler, an 8-bit period value, and one programmable counter channel with an 8-bit compare value. Each of the counter channels can be used as PWM output.

USART 0 and USART 1 are each configurable as either an SPI master/slave or a UART. They provide double buffering on both RX and TX and hardware flow control and are thus well suited to high-throughput full-duplex applications. Each USART has its own high-precision baud-rate generator, thus leaving the ordinary timers free for other uses. When configured as SPI slaves, the USARTs sample the input signal using SCK directly instead of using some oversampling scheme, and are thus well-suited for high data rates.

The **AES encryption/decryption core** allows the user to encrypt and decrypt data using the AES algorithm with 128-bit keys. The AES core also supports ECB, CBC, CFB, OFB, CTR, and CBC-MAC, as well as hardware support for CCM.

The **ADC** supports 7 to 12 bits of resolution with a corresponding range of bandwidths from 30-kHz to 4-kHz, respectively. DC and audio conversions with up to eight input channels (I/O controller pins) are possible. The inputs can be selected as single-ended or differential. The reference voltage can be internal, AVDD, or a single-ended or differential external signal. The ADC also has a temperature-sensor input channel. The ADC can automate the process of periodic sampling or conversion over a sequence of channels.

The **I^2C** module provides a digital peripheral connection with two pins and supports both master and slave operation. I^2C support is compliant with the NXP I^2C specification version 2.1 and supports standard mode (up to 100 kbps) and fast mode (up to 400 kbps). In addition, 7-bit device addressing modes are supported, as well as master and slave modes.

The ultralow-power **analog comparator** enables applications to wake up from PM2 or PM3 based on an analog signal. Both inputs are brought out to pins; the reference voltage must be provided externally. The comparator output is connected to the I/O controller interrupt detector and can be treated by the MCU as a regular I/O pin interrupt.

TYPICAL CHARACTERISTICS

RX CURRENT vs TEMPERATURE

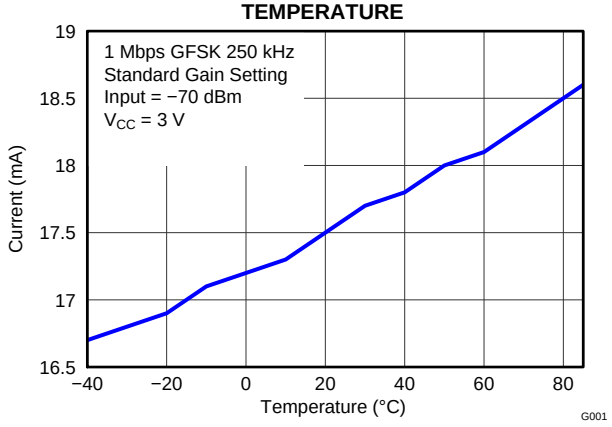


Figure 10.

TX CURRENT vs TEMPERATURE

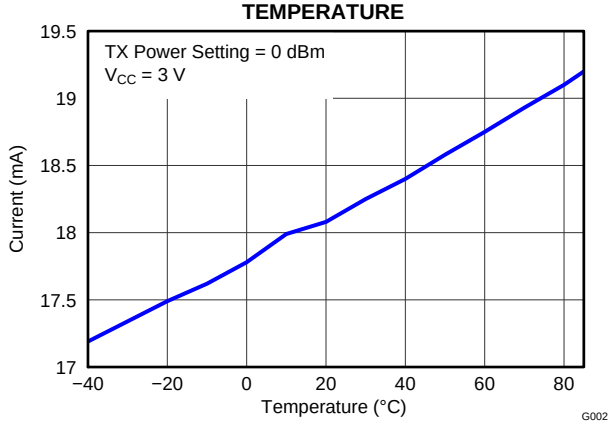


Figure 11.

RX SENSITIVITY vs TEMPERATURE

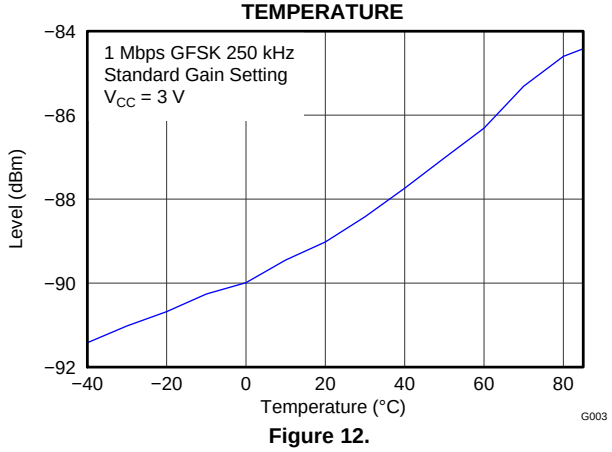


Figure 12.

TX POWER vs TEMPERATURE

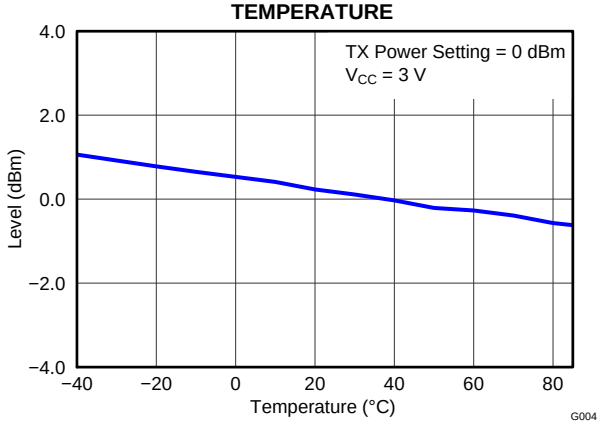


Figure 13.

RX CURRENT vs SUPPLY VOLTAGE

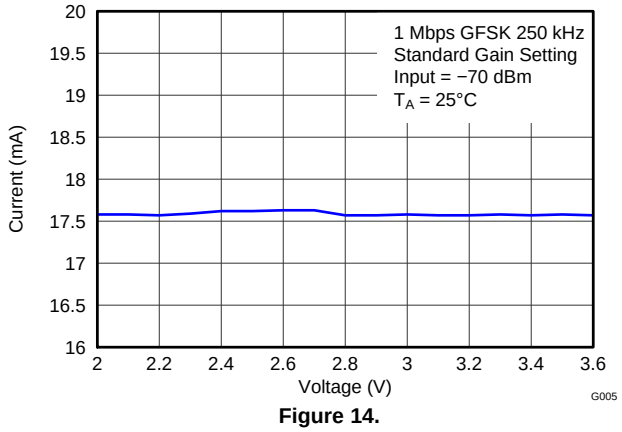


Figure 14.

TX CURRENT vs SUPPLY VOLTAGE

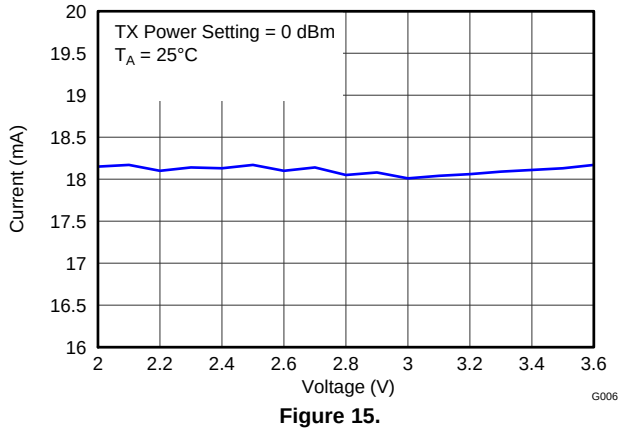


Figure 15.

TYPICAL CHARACTERISTICS (continued)

RX SENSITIVITY VS SUPPLY VOLTAGE

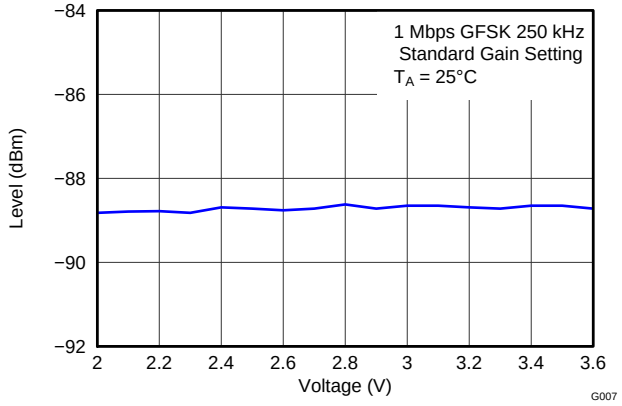


Figure 16.

TX POWER VS SUPPLY VOLTAGE

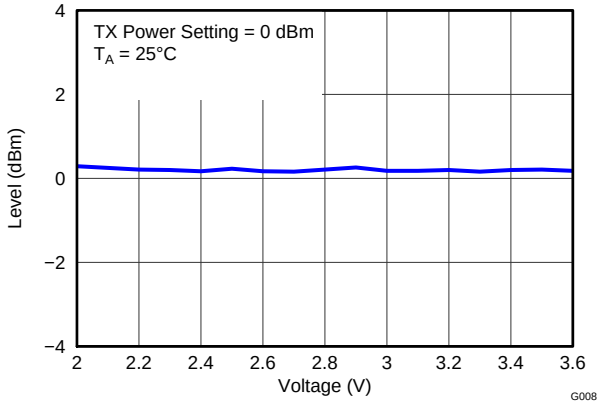


Figure 17.

RX SENSITIVITY VS FREQUENCY

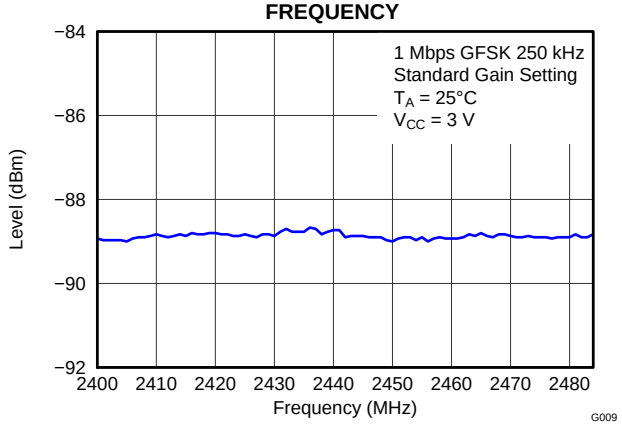


Figure 18.

TX POWER VS FREQUENCY

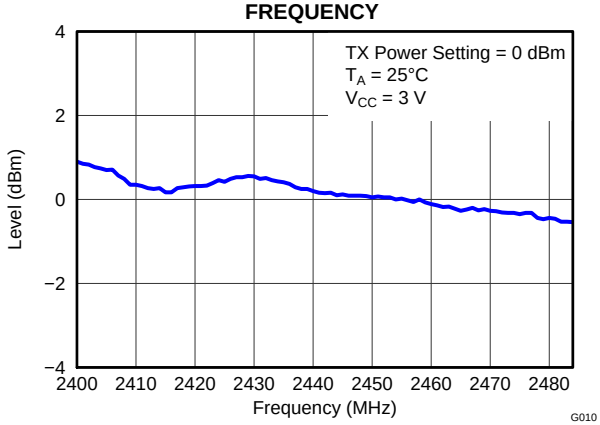


Figure 19.

Table 1. Output Power(1)(2)

TXPOWER Setting	Typical Output Power (dBm)
0xE1	0
0xD1	–2
0xC1	–4
0xB1	–6
0xA1	–8
0x91	–10
0x81	–12
0x71	–14
0x61	–16
0x51	–18
0x41	–20
0x31	–23

(1) Measured on Texas Instruments CC2541 EM reference design with T_A = 25°C, VDD = 3 V and f_c = 2440 MHz. See SWRU191 for recommended register settings.
(2) 1 Mbsp, GFSK, 250-kHz deviation, Bluetooth™ low energy mode, 1% BER

Table 2. Output Power and Current Consumption

Typical Output Power (dBm)	Typical Current Consumption (mA)(1)	Typical Current Consumption With TPS62730 (mA)(2)
0	18.2	14.3
–20	16.8	13.1

(1) Measured on Texas Instruments CC2541 EM reference design with T_A = 25°C, VDD = 3 V and f_c = 2440 MHz. See SWRU191 for recommended register settings.
(2) Measured on Texas Instruments CC2541 TPS62730 EM reference design with T_A = 25°C, VDD = 3 V and f_c = 2440 MHz. See SWRU191 for recommended register settings.

TYPICAL CURRENT SAVINGS WHEN USING TPS62730

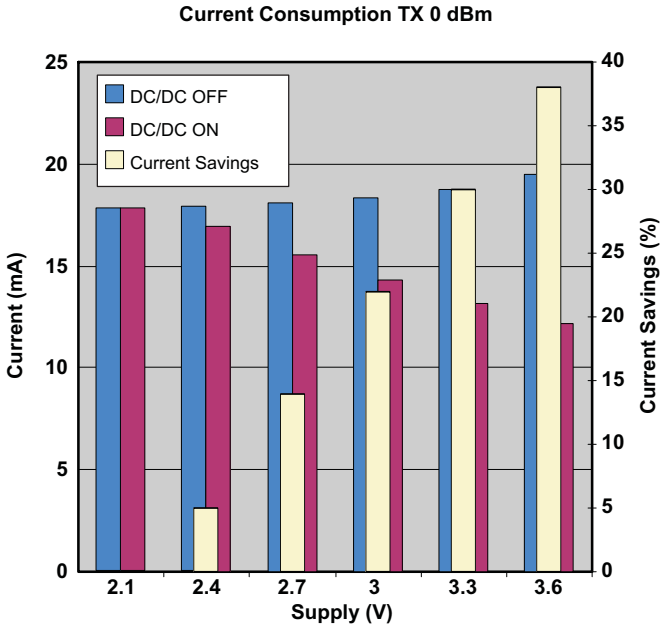


Figure 20. Current Savings in TX at Room Temperature

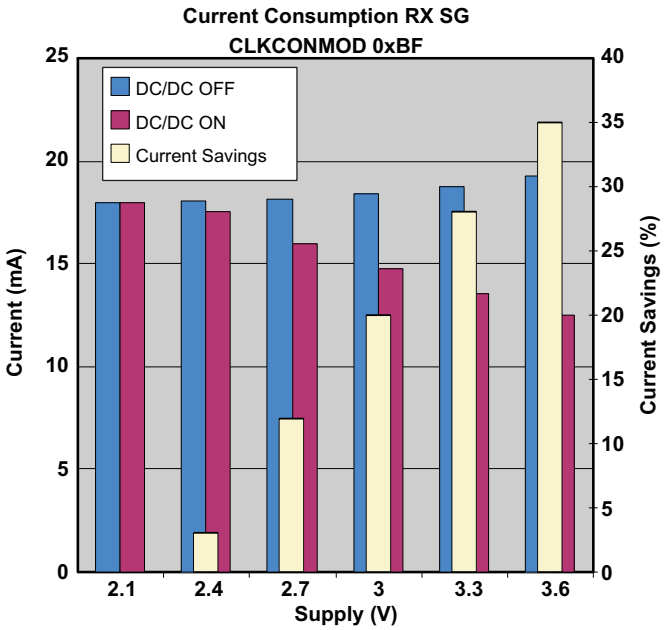
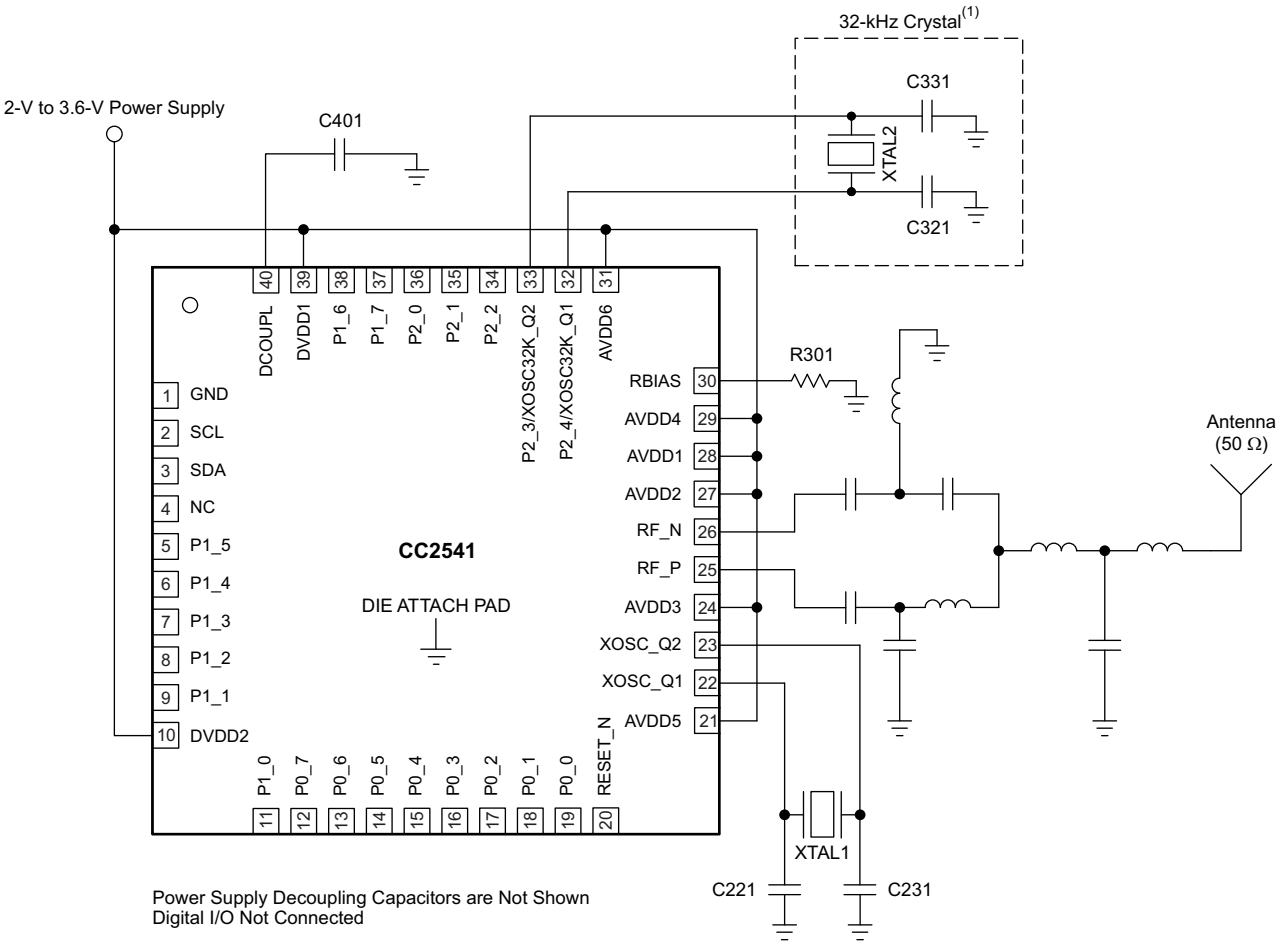


Figure 21. Current Savings in RX at Room Temperature

The application note (SWRA365) has information regarding the CC2541 and TPS62730 combo board and the current savings that can be achieved using the combo board.

APPLICATION INFORMATION

Few external components are required for the operation of the CC2541. A typical application circuit is shown in Figure 22.



(1) 32-kHz crystal is mandatory when running the BLE protocol stack in low-power modes, except if the link layer is in the standby state (Vol. 6 Part B Section 1.1 in [1]).

NOTE: Different antenna alternatives will be provided as reference designs.

Figure 22. CC2541 Application Circuit

Table 3. Overview of External Components (Excluding Supply Decoupling Capacitors)

Component	Description	Value
C401	Decoupling capacitor for the internal 1.8-V digital voltage regulator	1 µF
R301	Precision resistor ±1%, used for internal biasing	56 kΩ

Input/Output Matching

When using an unbalanced antenna such as a monopole, a balun should be used to optimize performance. The balun can be implemented using low-cost discrete inductors and capacitors. See reference design, CC2541EM, for recommended balun.

Crystal

An external 32-MHz crystal, XTAL1, with two loading capacitors (C221 and C231) is used for the 32-MHz crystal oscillator. See 32-MHz CRYSTAL OSCILLATOR for details. The load capacitance seen by the 32-MHz crystal is given by:

$$C_L = \frac{1}{\frac{1}{C_{221}} + \frac{1}{C_{231}}} + C_{parasitic} \quad (1)$$

XTAL2 is an optional 32.768-kHz crystal, with two loading capacitors (C321 and C331) used for the 32.768-kHz crystal oscillator. The 32.768-kHz crystal oscillator is used in applications where both very low sleep-current consumption and accurate wake-up times are needed. The load capacitance seen by the 32.768-kHz crystal is given by:

$$C_L = \frac{1}{\frac{1}{C_{321}} + \frac{1}{C_{331}}} + C_{parasitic} \quad (2)$$

A series resistor may be used to comply with the ESR requirement.

On-Chip 1.8-V Voltage Regulator Decoupling

The 1.8-V on-chip voltage regulator supplies the 1.8-V digital logic. This regulator requires a decoupling capacitor (C401) for stable operation.

Power-Supply Decoupling and Filtering

Proper power-supply decoupling must be used for optimum performance. The placement and size of the decoupling capacitors and the power supply filtering are very important to achieve the best performance in an application. TI provides a compact reference design that should be followed very closely.

References

1. *Bluetooth*® Core Technical Specification document, version 4.0
   http://www.bluetooth.com/SiteCollectionDocuments/Core_V40.zip
2. CC253x System-on-Chip Solution for 2.4-GHz IEEE 802.15.4 and ZigBee® Applications/CC2541 System-on-Chip Solution for 2.4-GHz *Bluetooth* low energy Applications (SWRU191)
3. Current Savings in CC254x Using the TPS62730 (SWRA365).

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REVISION HISTORY

Changes from Original (January 2012) to Revision A	Page
• Changed data sheet status from Product Preview to Production Data	1

Changes from Revision A (February 2012) to Revision B	Page
• Changed the Temperature coefficient Unit value From: mV/°C To: / 0.1°C	10
• Changed Figure 22 text From: Optional 32-kHz Crystal To: 32-kHz Crystal	24

Changes from Revision B (August 2012) to Revision C	Page
• Changed the "Internal reference voltage" TYP value From 1.15 V To: 1.24 V	12
• Changed pin XOSC_Q1 Pin Type From Analog O To: Analog I/O, and changed the Pin Description	17
• Changed pin XOSC_Q2 Pin Type From Analog O To: Analog I/O	17

Changes from Revision C (November 2012) to Revision D	Page
• Changed the RF TRANSMIT SECTION, Output power TYP value From: –20 To: –23	8
• Changed the RF TRANSMIT SECTION, Programmable output power range TYP value From: 20 To: 23	8
• Added row 0x31 to Table 1	22

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CC2541F128RHAR	ACTIVE	VQFN	RHA	40	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-3-260C-168 HR		CC2541 F128	Samples
CC2541F128RHAT	ACTIVE	VQFN	RHA	40	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-3-260C-168 HR		CC2541 F128	Samples
CC2541F256RHAR	ACTIVE	VQFN	RHA	40	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-3-260C-168 HR		CC2541 F256	Samples
CC2541F256RHAT	ACTIVE	VQFN	RHA	40	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-3-260C-168 HR		CC2541 F256	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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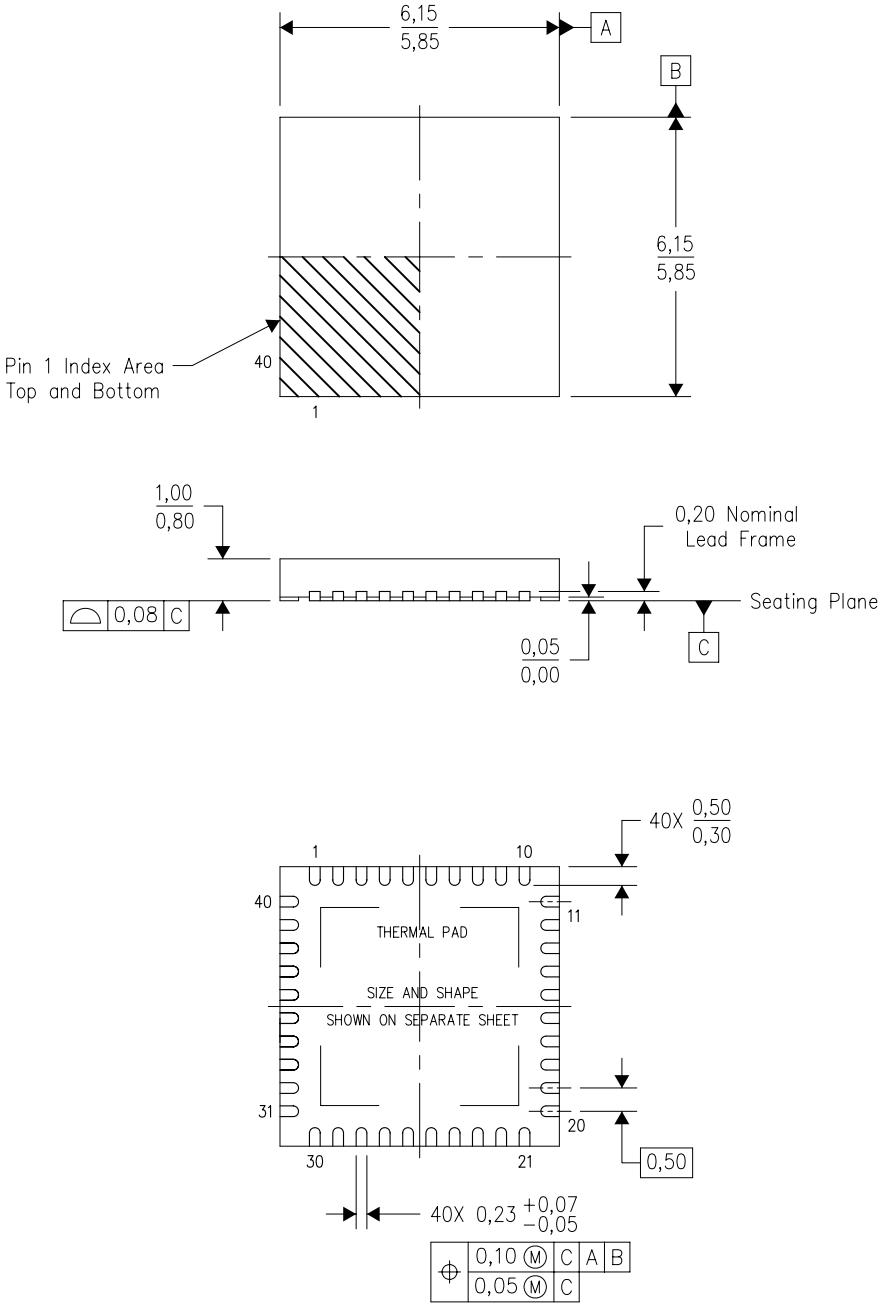
RHA (S–PVQFN–N40) PLASTIC QUAD FLATPACK NO–LEAD



Bottom View

4204276/E 06/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. QFN (Quad Flatpack No–Lead) Package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
F. Package complies to JEDEC MO–220 variation VJJD–2.

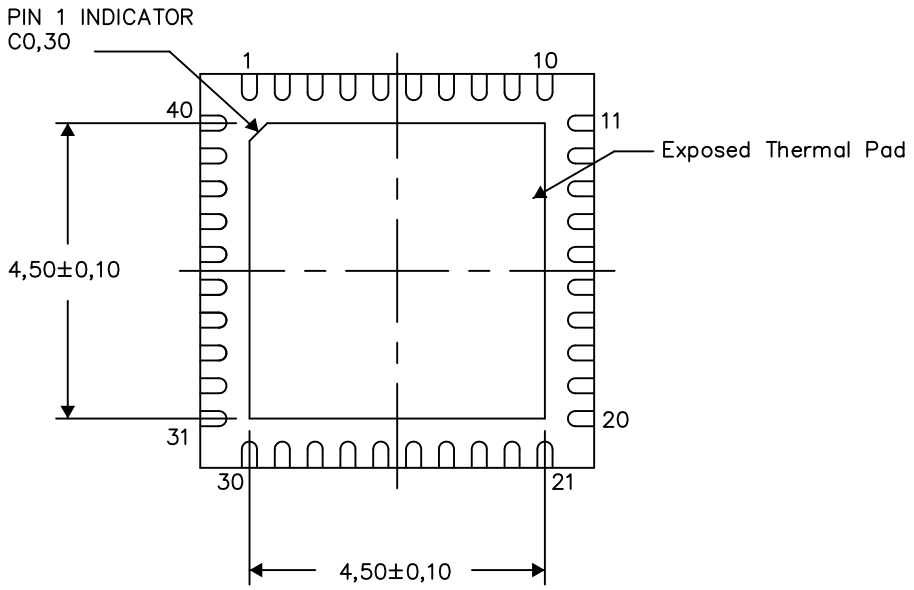
RHA (S–PVQFN–N40) PLASTIC QUAD FLATPACK NO–LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No–Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



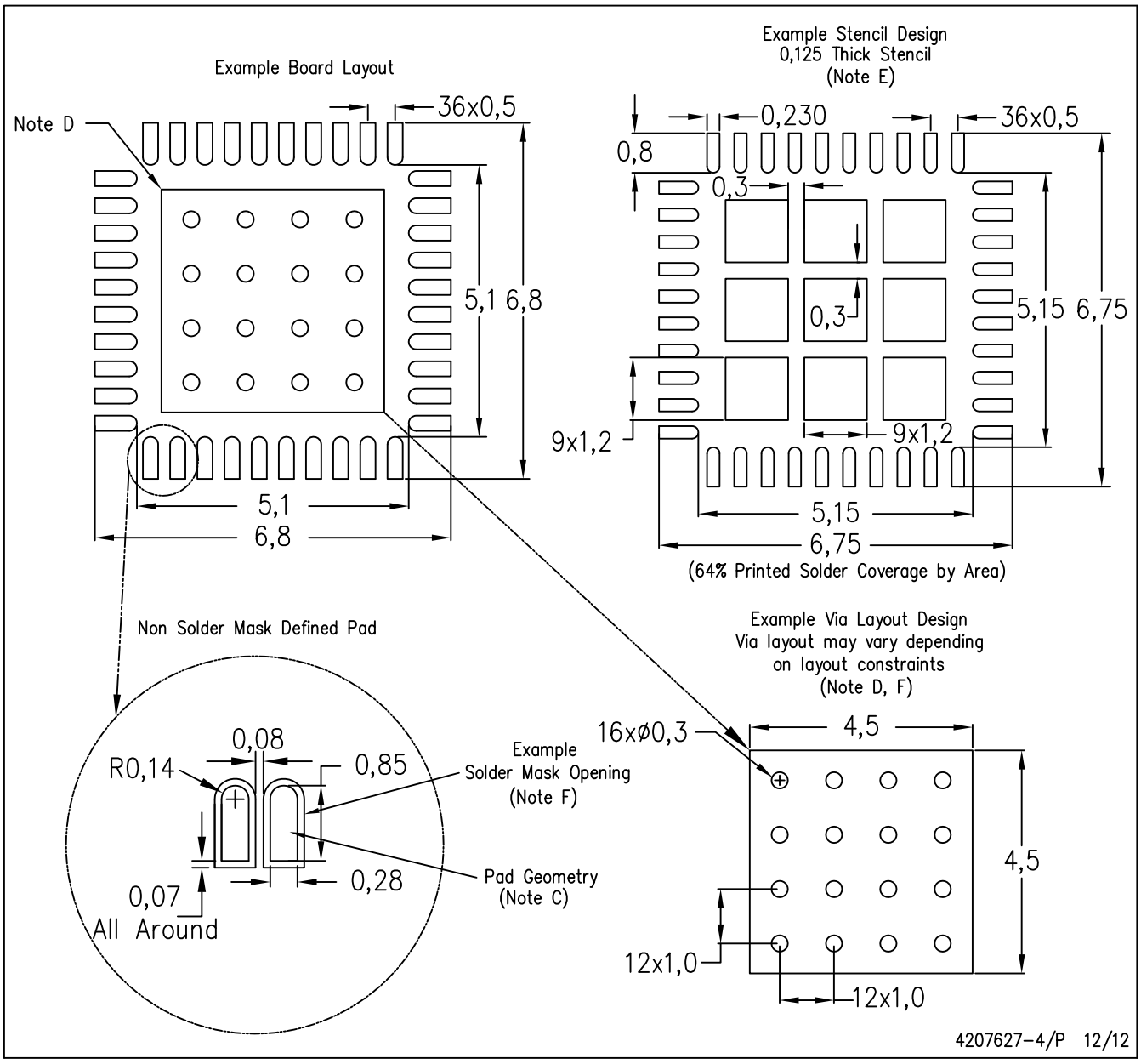
Bottom View

Exposed Thermal Pad Dimensions

4206355–4/U 12/12

NOTES: A. All linear dimensions are in millimeters

RHA (S–PVQFN–N40) PLASTIC QUAD FLATPACK NO–LEAD



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat–Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http://www.ti.com>.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
F. Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

WNZ7915/7916

Product Specification

WLAN 11b/g/n SDIO MODULE

Feedback of customer's Confirmation **We accept the specification after Confirmed.**		
Customer	**Customer signature**	**Approved Date**

Contents

1. General Description

WNZ7915 product Accord with FCC CE and is 150 wireless SDIO adapter which has lower power consumption, high linearity output power, accords with IEEE802.11B/G/N, and supports IEEE802.11i safety protocol, along with IEEE 802.11e standard service quality. It connects with other wireless device which accorded with these standards together, supports the new data encryption on 64/128 bit WEP and safety mechanism on WPA-PSK/WPA2-PSK, WPA/WPA2.Its wireless transmitting rate rises 150M, equivalent to 10 times of common 11b product. The inner AI high gain ceramics antenna adapts different kinds of work environment. It's easy and convenient to link to wireless network for the users using desktop, laptop and other device that needs connect to wireless network.

2. The range of applying

MID, networking camera, STB GPS, E-book, Hard disk player, Network Radios, PSP, etc, the device which need be supported by wireless networking.

3. Features

Feature	**Implementation**
Power supply	VCC_3.3V +-0.2V
Clock source	40MHz
Temperature range	Work temperature: -20ºC---70ºC Storage temperature -55°C ~ +125°C
Package	SMT 13 pins
WLAN features	
General features	CMOS MAC, Baseband PHY, and RF in a single chip for IEEE 802.11b/g/n compatible WLAN Complete 802.11n solution for 2.4GHz band 72.2Mbps receive PHY rate and 72.2Mbps transmit PHY rate using 20MHz bandwidth 150Mbps receive PHY rate and 150Mbps transmit PHY rate using 40MHz bandwidth Compatible with 802.11n specification Backward compatible with 802.11b/g devices while operating in 802.11n mode

Host Interface	Complies with SDIO 1.1/ 2.0/ 3.0; GSPI interface
Standards Supported	■IEEE 802.11b/g/n compatible WLAN ■IEEE 802.11e QoS Enhancement (WMM) ■802.11i (WPA, WPA2). Open, shared key, and pair-wise key authentication services
WLAN MAC Features	■Frame aggregation for increased MAC efficiency (A-MSDU, A-MPDU) ■Low latency immediate High-Throughput Block Acknowledgement (HT-BA) ■PHY-level spoofing to enhance legacy compatibility ■Power saving mechanism ■Channel management and co-existence ■Transmit Opportunity (TXOP) Short Inter-Frame Space (SIFS) bursting for higher multimedia bandwidth
WLAN PHY Features	■IEEE 802.11n OFDM ■One Transmit and one Receive path (1T1R) ■20MHz and 40MHz bandwidth transmission ■Short Guard Interval (400ns) ■DSSS with DBPSK and DQPSK, CCK modulation with long and short preamble ■ OFDM with BPSK, QPSK, 16QAM, and 64QAM modulation. Convolutional Coding Rate: 1/2, 2/3, 3/4, and 5/6 ■Maximum data rate 54Mbps in 802.11g and 150Mbps in 802.11n ■Switch diversity for DSSS/CCK ■Hardware antenna diversity ■Selectable receiver FIR filters ■Programmable scaling in transmitter and receiver to trade quantization noise against increased probability of clipping Fast ■receiver Automatic Gain Control (AGC)

	■On-chip ADC and DAC

4. DC Characteristics

Symbol	Parameter	Minimum	Typical	Maximum	Units
VD33A, VD33D	3.3V I/O Supply Voltage	3.135	3.3	3.465	v
VD12A, VD12D	1.2V Core Supply Voltage	1.10	1.2	1.32	v
VD15A, VD15D	1.5V Supply Voltage	1.425	1.5	1.575	v
IDD33	3.3V Rating Current	-	-	600	mA

5.The main performance of product

Item	Description
The supported protocol and standard	IEEE 802.11n, IEEE 802.11g,EE 802.11b
Interface type	SDIO 1.1/ 2.0/ 3.0
The range of frequency	2.4-2.484GHZ
The amount of working Channel	1-11（America, Canada）;1-13（China, Europe）;1-14（Japan）
Data Modulation	OFDM/DBPSK/DQPSK/CCK
Working Mode	Infrastructure, Ad-Hoc
The transmitting rate	135/54/48/36/24/18/12/9/6 /1M（self-adapting）
Spread spectrum	DSSS
Sensitivity @PER	54/135M:-74dBm@10%PER, 11M:-85dBm@8%PER 6M: -88dBm@10%PER , 1M: -90dBm@8%PER
RF Power	135M:15dBM, 54M:15dBM, 11M:19dBM
Throughput	90Mbps(external 2dbi antenna ,damping 40dbm in Shielding box)

The connect type of Antenna	Connect to the external antenna through the half hole
LED indicator	status indicator
The transmit distance	Indoor 100M, Outdoor 300M, according the local environment
Working Power consumption	180MA
MENS(L*W*H)	14.1MM*12.5*0.8MM
The chipset model	RTL8189ES-CG

6. DC/RF characteristics

Terms	**Contents**			
Specification : IEEE802.11b				
Mode	DSSS / CCK			
Frequency	2412 – 2484MHz			
Data rate	1, 2, 5.5, 11Mbps			
DC Characteristics	min	Typ.	max.	unit
TX mode	305	309	311	mA
Rx mode	175	180	181	mA
Standby mode	140	145	146	uA
Specification : IEEE802.11g				
Mode	OFDM			
Frequency	2412 - 2484MHz			
Data rate	6, 9, 12, 18, 24, 36, 48, 54Mbps			
DC Characteristics	min	Typ.	max.	unit
TX mode	244	245	245	mA
Rx mode	182	185	186	mA
Standby mode	143	145	146	uA
Specification : IEEE802.11n				
Mode	OFDM			
Frequency	2412 - 2484MHz			
Data rate	6.5, 13, 19.5, 26, 39, 52, 58.5, 65Mbps			
DC Characteristics	min	Typ.	max.	unit
TX mode	240	242	244	mA
Rx mode	189	190	191	mA
Standby mode	144	145	146	uA

7.The block diagram of product principle

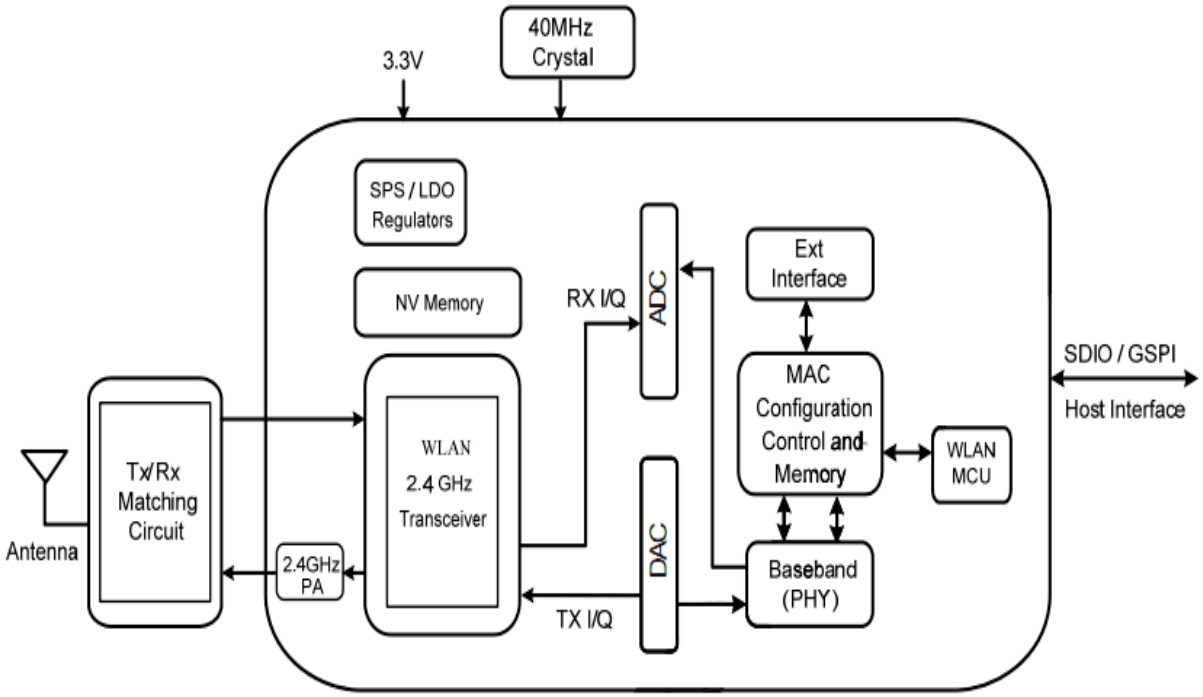
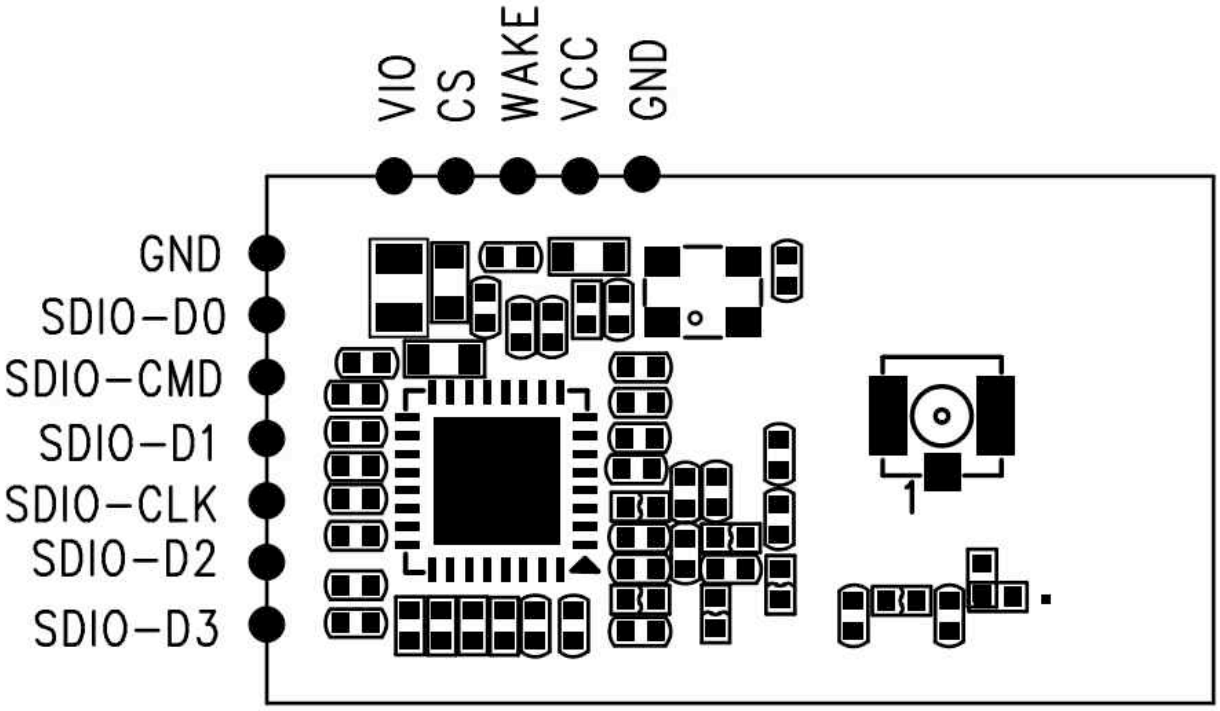


Figure 1. Single-Band 11n (1x1) Solution

8.The supported platform

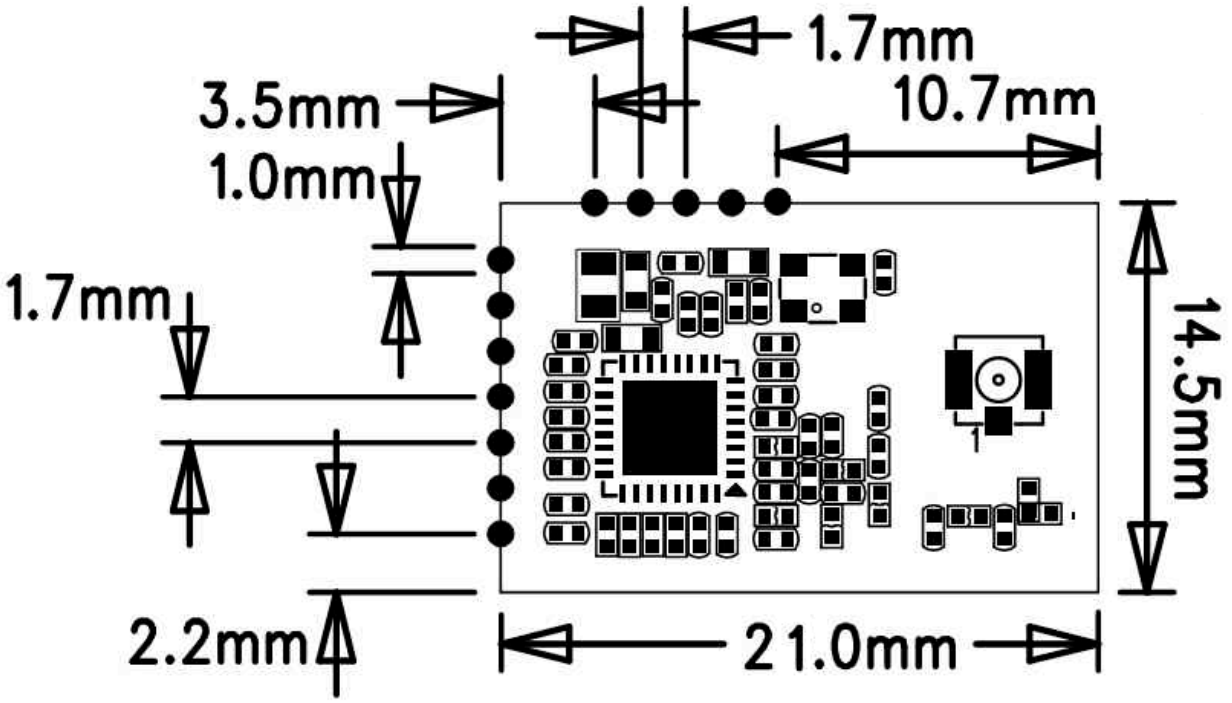
Operating System	CPU Framework	Driver
WIN2000/XP/VISTA/WIN7	X86 Platform	Enable
LINUX2.4/2.6	ARM, MIPSII	Enable
WINCE5.0/6.0	ARM ,MIPSII	Enable

9.The definition of product Pin

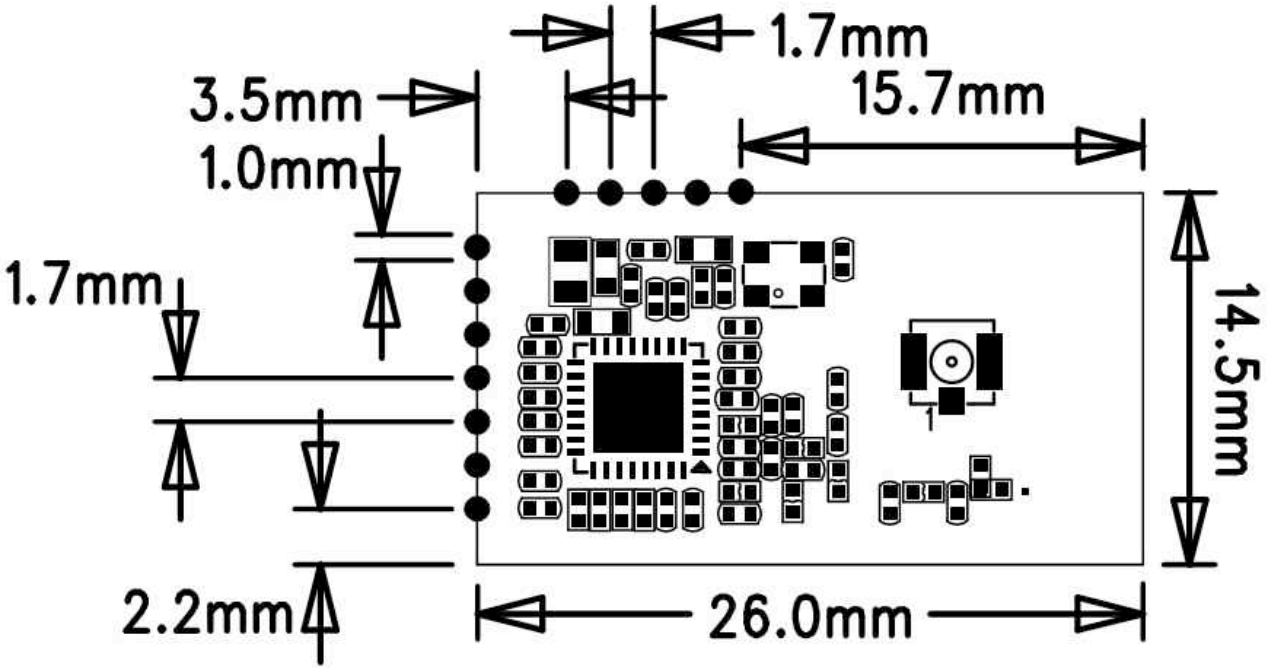


Top and bottom view

10.The Structure and Size of product

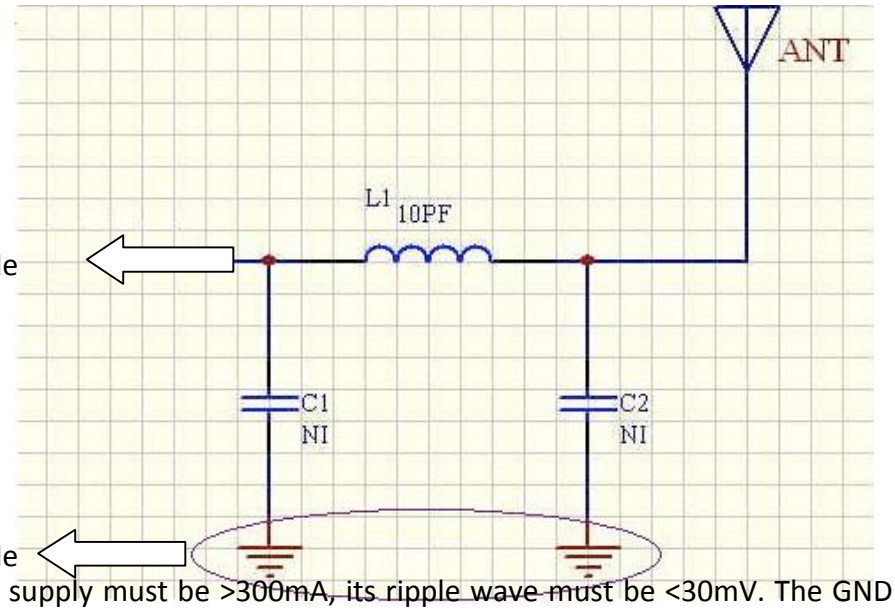


WNZ7916 (no on-board antenna)



WNZ7915 / WNZ7915(E)

11: The 6th Pin connect to antenna, please refer to design demand



Connect to the 6th pin of Module

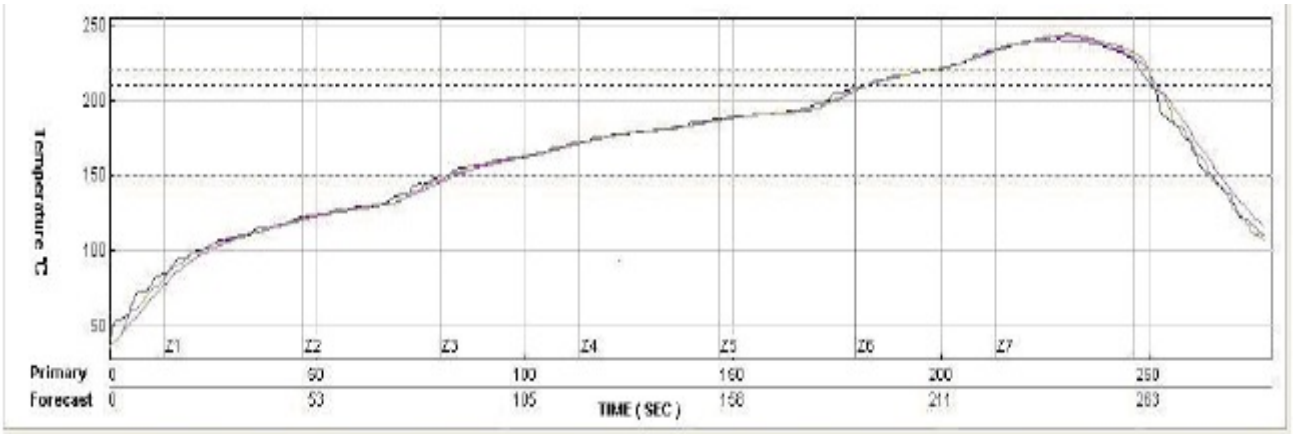
Connect to the 5th pin of Module

a) The current of 3.3V power supply must be >300mA, its ripple wave must be <30mV. The GND pins of module and external antenna need to be an incorporated part. The ground plane should be larger, module and antenna should keep far away from interference source.

b) The sixth pin is 2.4G high frequency output, coplanar impedance of layout line between this pin to antenna interface should be 50Ω, we suggest use arc line or straight line, and beside the line there will be ground plane that its length as shout as possible, the longest length is no more than 50mm.

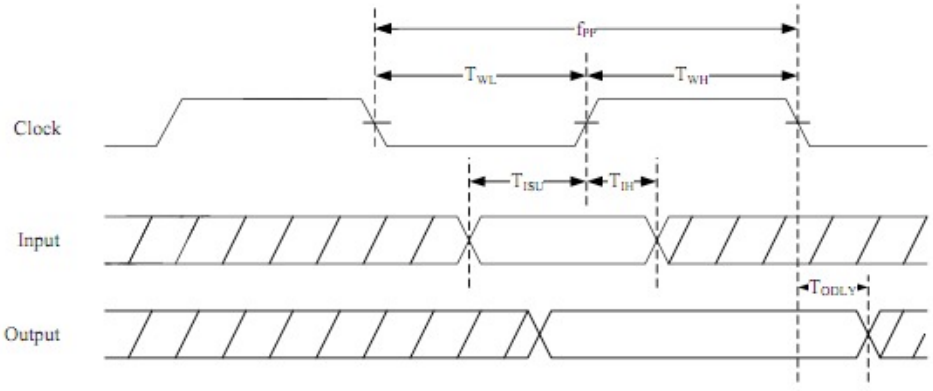
c) L1, C1, C2 constitute a π-type network that we preset, please make it close to antenna interface, this π-type network is used to match the antenna parameters and control the radiation. It should be adjusted according to the real condition when being used. Normally you can only mount L1 that its parameters are: 10pF, NP0 material. No need C1 and C2

12.Tpical Solder Reflow Profile



TCx	RAMP		SOAP Between 150 to 210 ℃		Reflow 220℃		Peak Temperature ℃	
2	1.4	-7%	99.4	31%	53.8	38%	243.1	82%
3	1.4	-4%	100.5	35%	51.5	15%	241.0	20%
4	1.4	-5%	101.4	38%	54.4	44%	244.7	83%
Different in Temp	0.04		1.99		2.92		3.65	
P.2	1.4	-7%	99.4	31%	53.8	38%	243.1	82%
P.3	1.4	-4%	100.5	35%	51.5	15%	241.0	20%
P.4	1.4	-5%	101.4	38%	54.4	44%	244.7	83%
Different in Temp	0.04		1.99		2.92		3.65	

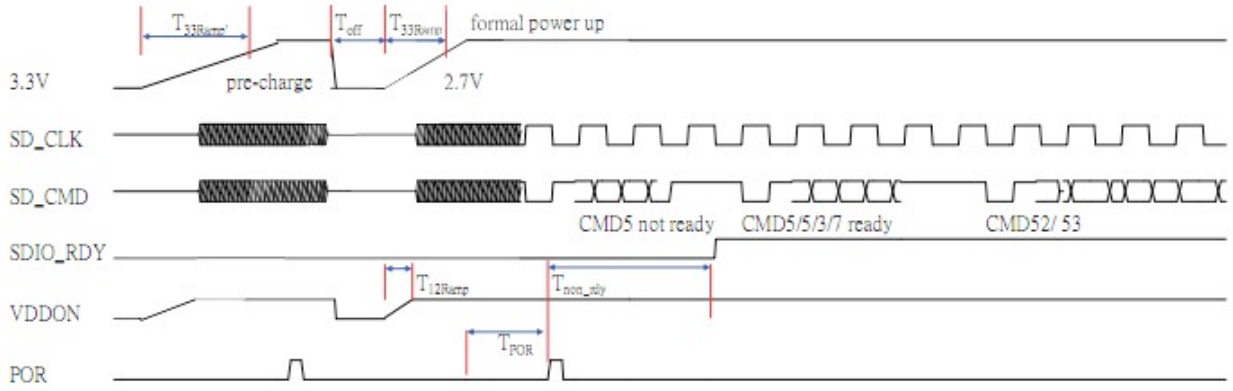
13. **I/O Interface Characteristics**



SDIO/GSPI Interface Characteristics

NO	Parameter	Mode	MIN	MAX	Unit
f_{PP}	Clock frequency	Default	0	25	MHz
		HS	0	50	MHz
T_{WL}	Clock low time	DEF	10		ns
		HS	7		ns
T_{WH}	Clock high time	DEF	10		ns
		HS	7		
T_{ISU}	Input setup time	DEF	5		ns
		HS	6		
T_{IH}	Input hold time	DEF	5		ns
		HS	2		
T_{ODLY}	Output delay time	DEF		14	ns
		HS		14	

The SDIO Interface Timing Parameters



SDIO Interface Characteristics

	Min	Typical	Max	Unit
T_{33ramp}'	--	--	No Limit	ms
T_{off}	250	500	1000	ms
T_{33ramp}	0.1	0.5	2.5	ms
T_{12ramp}	0.1	0.5	1.5	ms
T_{por}	2	2	8	ms
$T_{non-rdy}$	1	2	10	ms

SDIO Interface Power On Timing Parameters

14. Order Information

Part No	Description
WNZ-7915	On-bard Antenna 出廠預設使用板载天线
WNZ-7915 E	Using external Antenna 出廠預設使用外挂天线
WNZ-7916	Using external Antenna, cut on-board Antenna 外挂天线

15. Antenna Configuration for WNZ-7915